

PIXEL  
2016

# Highlights

G. Iacobucci  
Université de Genève



UNIVERSITÉ  
DE GENÈVE

FACULTÉ DES SCIENCES  
Département de physique  
nucléaire et corpusculaire

# Workshop format

- I liked very much the format of PIXEL2016, which allowed discussion of
  - ▶ present/past/future pixel detectors
  - ▶ ample time for physics motivations and achievements
  - ▶ detector layouts
  - ▶ sensors R&D
  - ▶ X-ray science
  - ▶ ...

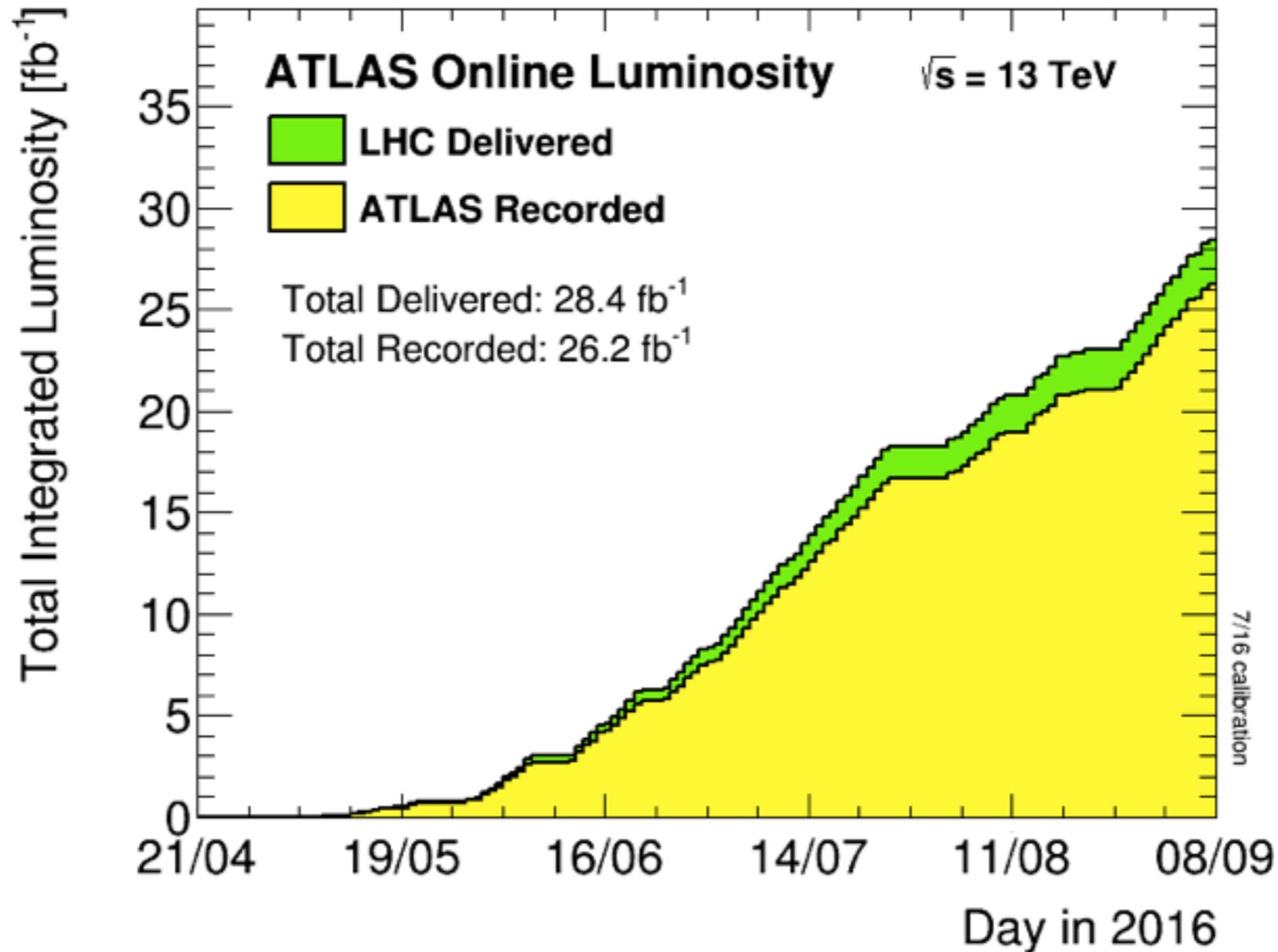
Ideal for (young) people working on the hardware.

Congratulations to the organisers

for the ideal format and the successful workshop

# ATLAS and CMS running

The context



LHC is delivering  $\sim 0.4 \text{ fb}^{-1}/\text{day}$  !!

very clever people in the LHC control room

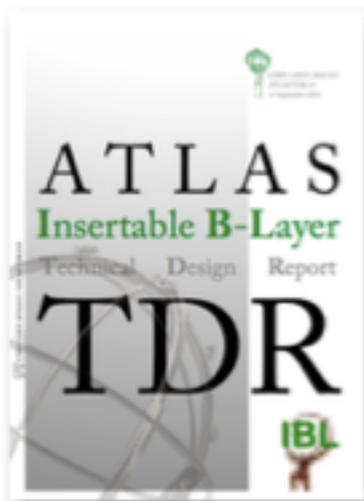
need of very clever people in the experiment's control rooms

- ▶ ... **fun** ? Life in LHC control rooms is **VERY hard**.
  - ➔ We all should be EXTREMELY grateful to all the colleagues operating these fancy and delicate detectors. Annalisa, Kerstin, János and Giacomo showed us how many problems need to be solved for an efficient operation.
    - ➔ I take the example of the ATLAS IBL, my experiment:
      - stave distortion vs. temperature (→ K. Lantzsch)
      - front-end LV current drift with exceeding TID (→ K. Dette)
      - prevention: mitigation of bandwidth limitation in B-layer (→ A. La Rosa)

life is hard but

## Summary (from A. La Rosa talk)

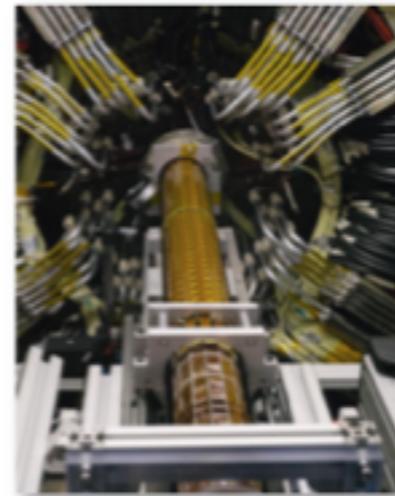
September 2010



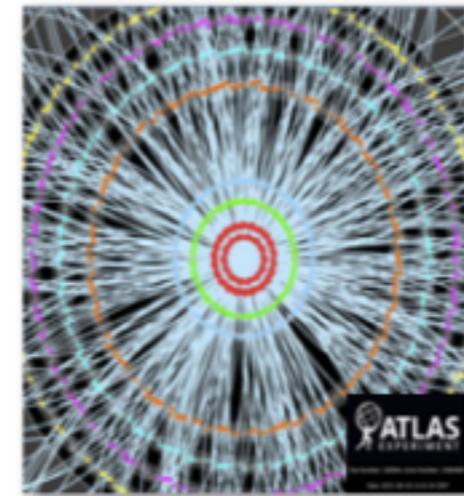
Mid 2012



May 2014



Since May 2015

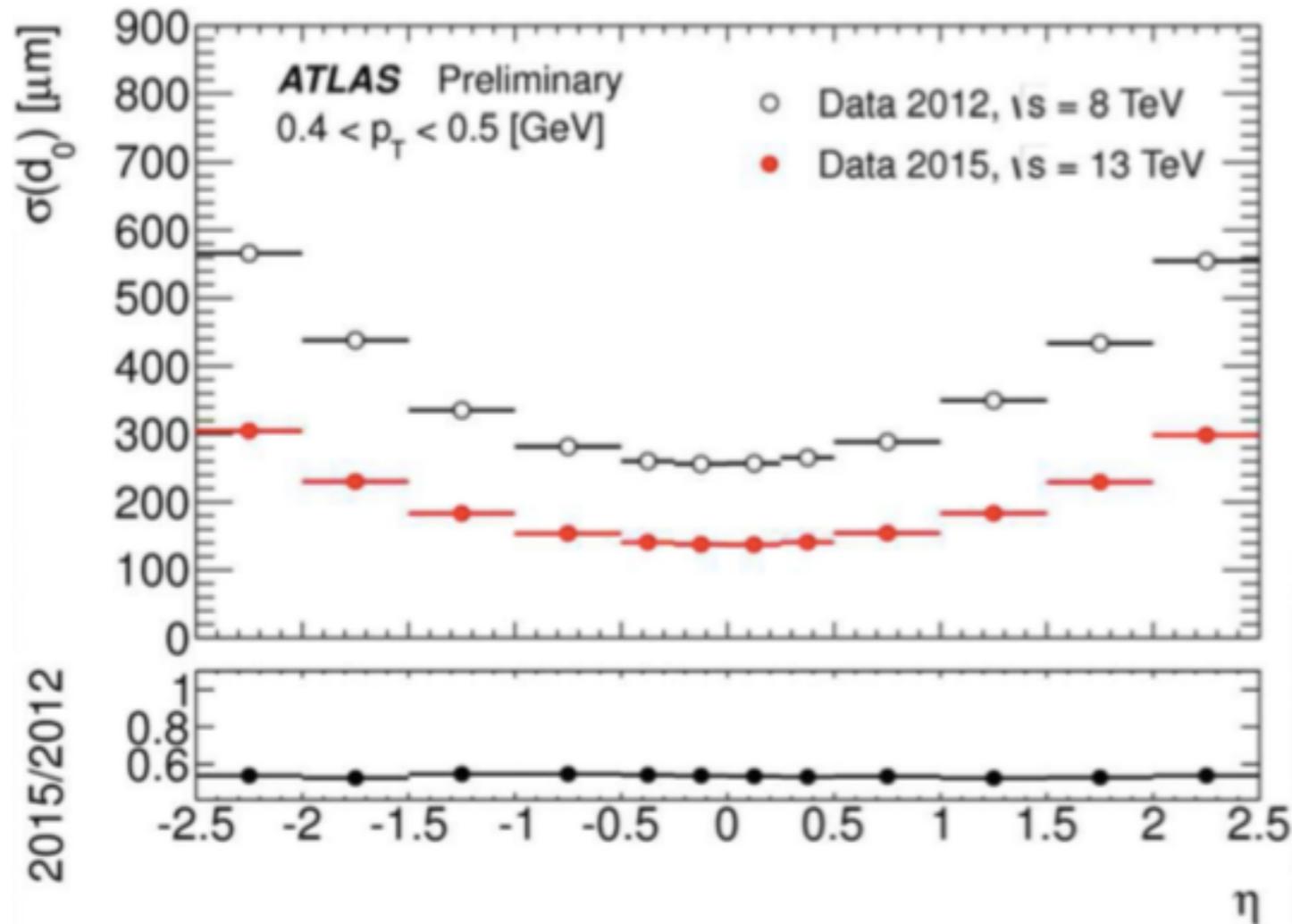


The Long-Shutdown-1 was realized as an opportunity and finally a great success for the Pixel Detector upgrade:

- **4<sup>th</sup> Layer Pixel (IBL) successfully installed and in operation with good performance**
- **First and successful use-case of 3D-Si sensors in HEP experiment !**

Now 3D also in: CMS-TOTEM PPS from next shutdown → Fabio Ravera  
& ATLAS-AFP → Sebastian Grinstein

# But life is also rewarding



**$d_0$  resolution vs.  $\eta$**

**Red: with IBL**

**Black: without IBL**

factor  $\sim 2$  improvement in track  $d_0$  impact parameter

▶ talk by Soshi Tsuno:

➔ 65% of analyses uses b-tagging, for which the PIXEL detector is essential, in particular for multi b-tagged processes:

If Run-1 result is “scaled” to 13TeV collisions (that is, **no IBL**),

Simple scaling :  $\sigma_{13\text{TeV}} \sim 8 \times \sigma_{8\text{TeV}}$

**Scaled Run-1 limit (no IBL) reaches :**  
 $m(\tilde{g}) = \sim 1600\text{GeV} @95\% \text{ C.L.}$   
(without IBL)

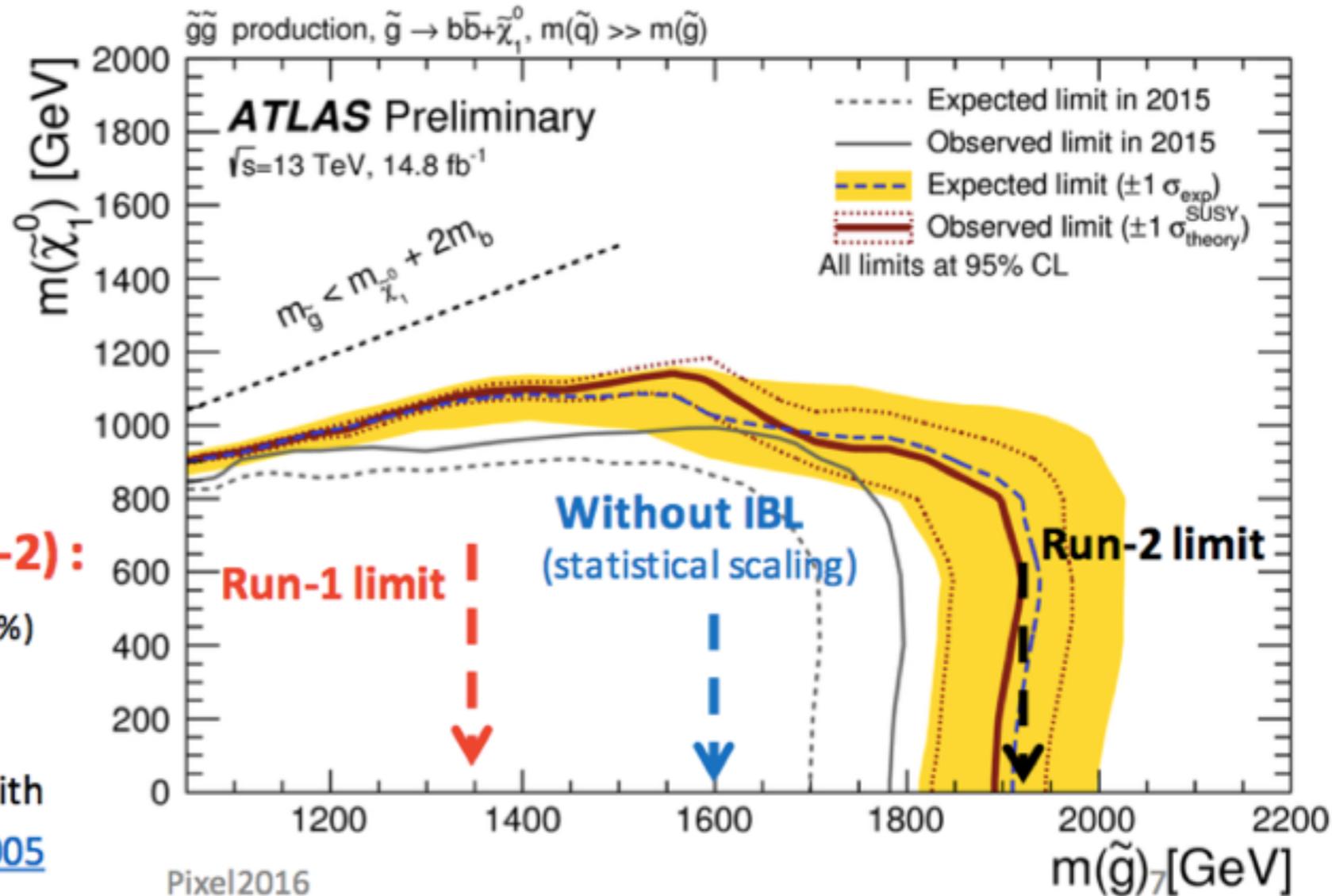
**Big impact on introducing IBL (Run-2) :**

$m(\tilde{g}) : 1900\text{GeV v.s. } 1600\text{GeV} \text{ (%)}$   
(plus analysis improvement)

(%) this scaling is more or less consistent with

[ATL-PHYS-PUB-2015-005](#)

September.05.2016





# Operational Experience with the CMS Pixel Detector

*János Karáncsi*

*On Behalf of the CMS Collaboration*

*Institute for Nuclear Research, H. A. S. (ATOMKI),*

*University of Debrecen*

PIXEL 2016, Sestri Levante (Italy), 5 September 2016

OTKA K109803

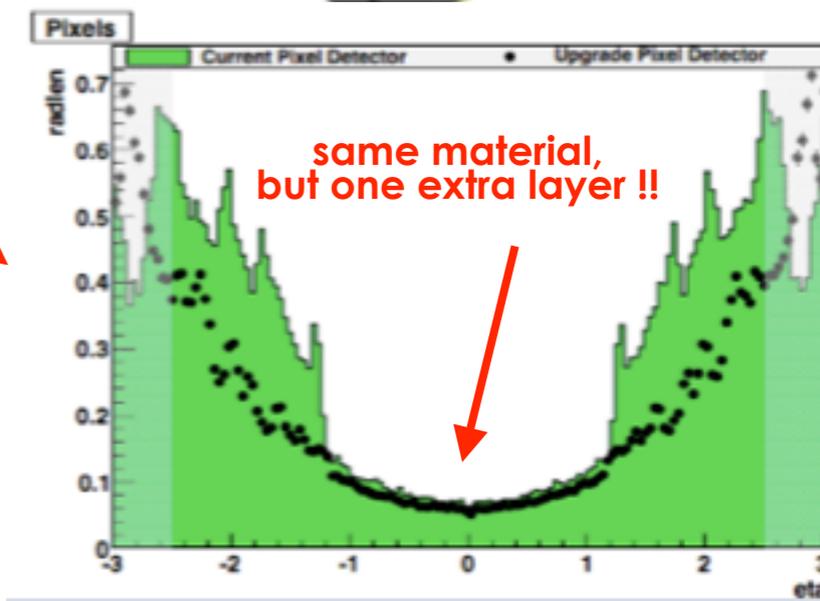
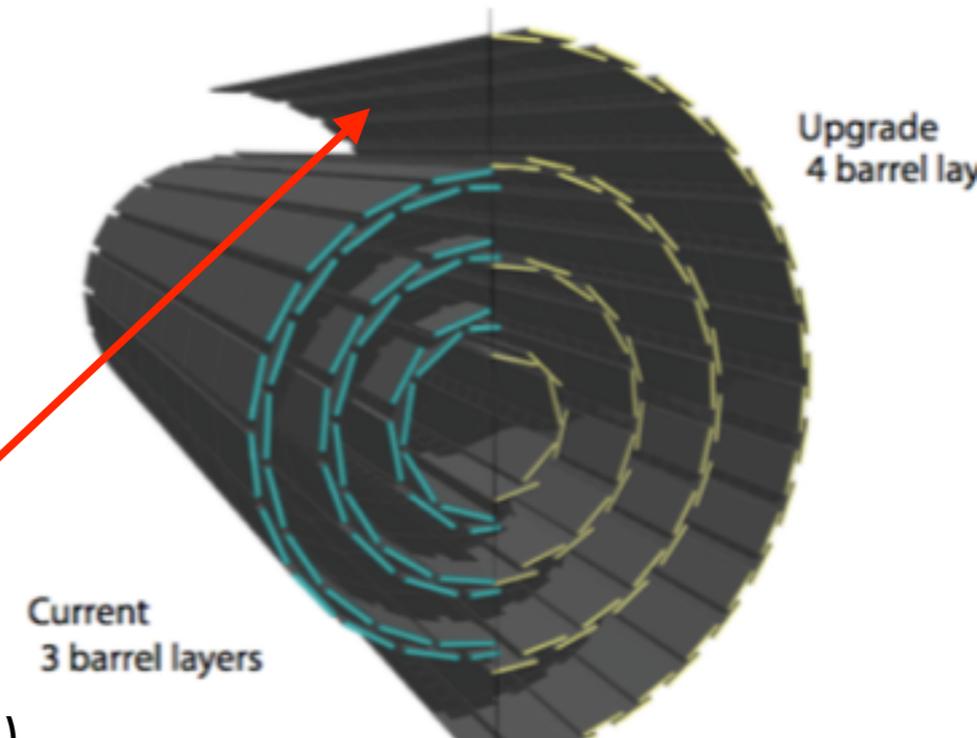
## Similarly for CMS Pixel:

- successful commissioning in Run2
- working fraction is high: 98.7%
- very good overall performance

the near future

In LHC Phase 1, we expect  $2 \cdot 10^{34} \text{cm}^{-2} \text{s}^{-1}$ , which exceeds the capability of present CMS Chip (ROC) and data links

- ▶ New pixel for CMS to maintain or improve at higher lumi present performance (→ V.R. Tavolaro, A. Starodumov).
- ▶ Unchanged:
  - ➔ pixel size, sensor technology, module concept
- ▶ New features:
  - ➔ New readout chip for higher rate capability
  - ➔ Additional barrel layer and endcap disk
  - ➔ First layer closer to interact. point (30 → 22.5mm)
  - ➔ Reduced material budget; new CO<sub>2</sub> cooling
  - ➔ Lower operational threshold



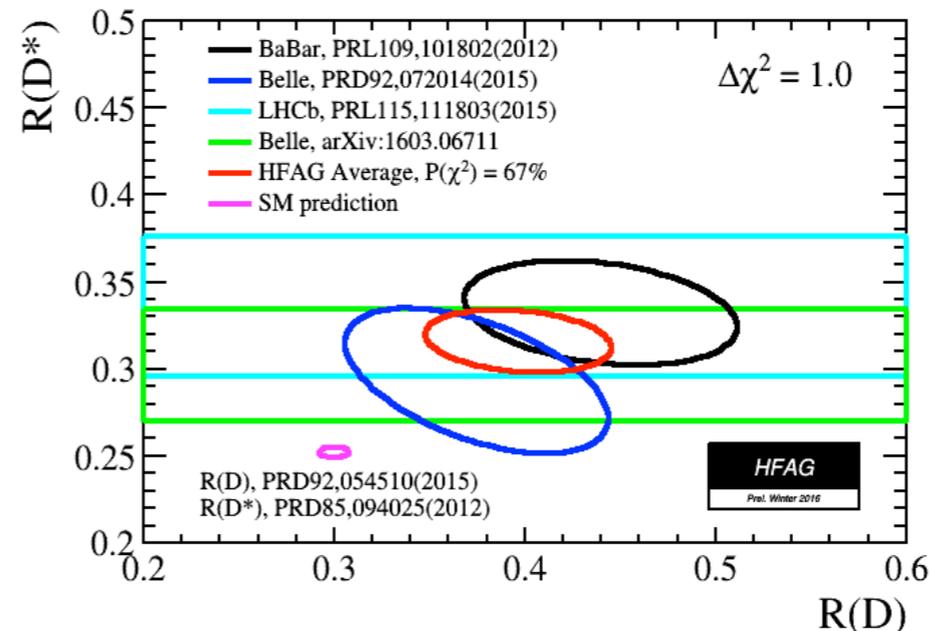
Module production reaching completion.

Installation during 2016-2017 EYETS

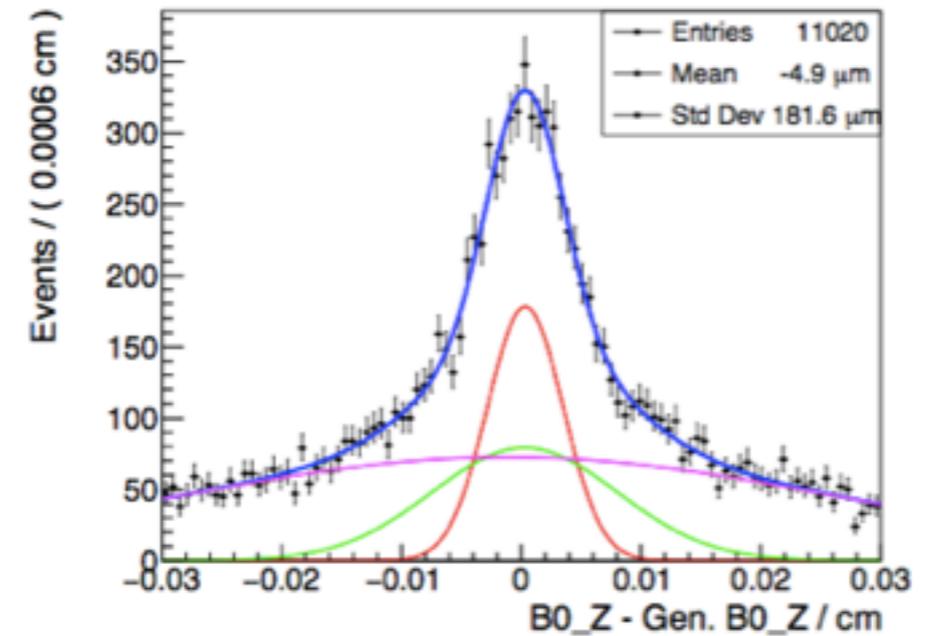
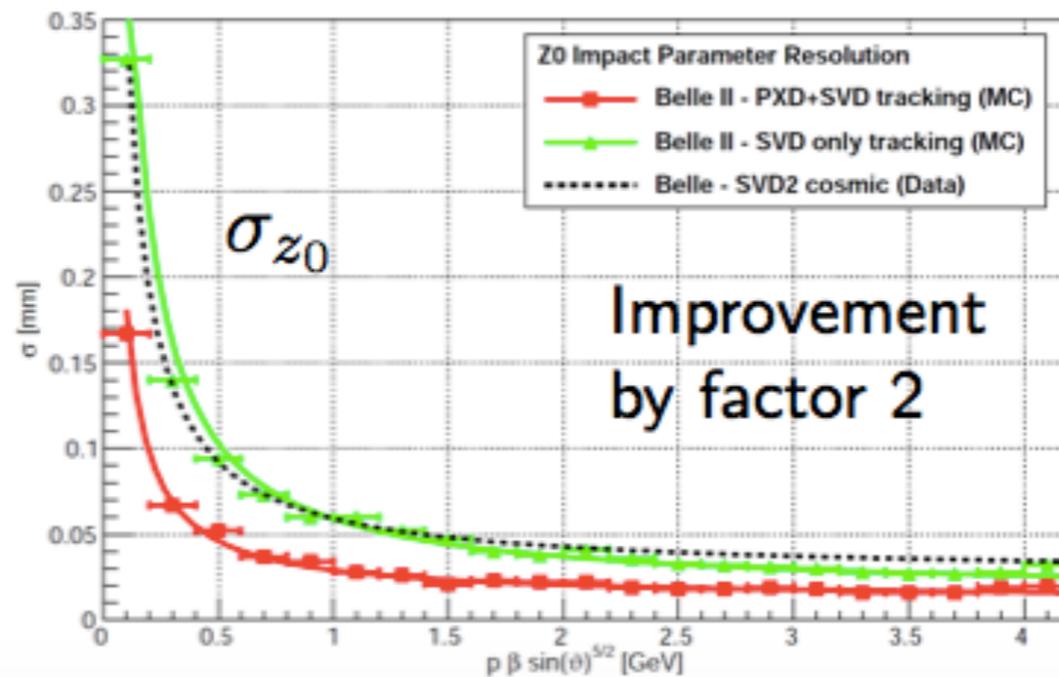
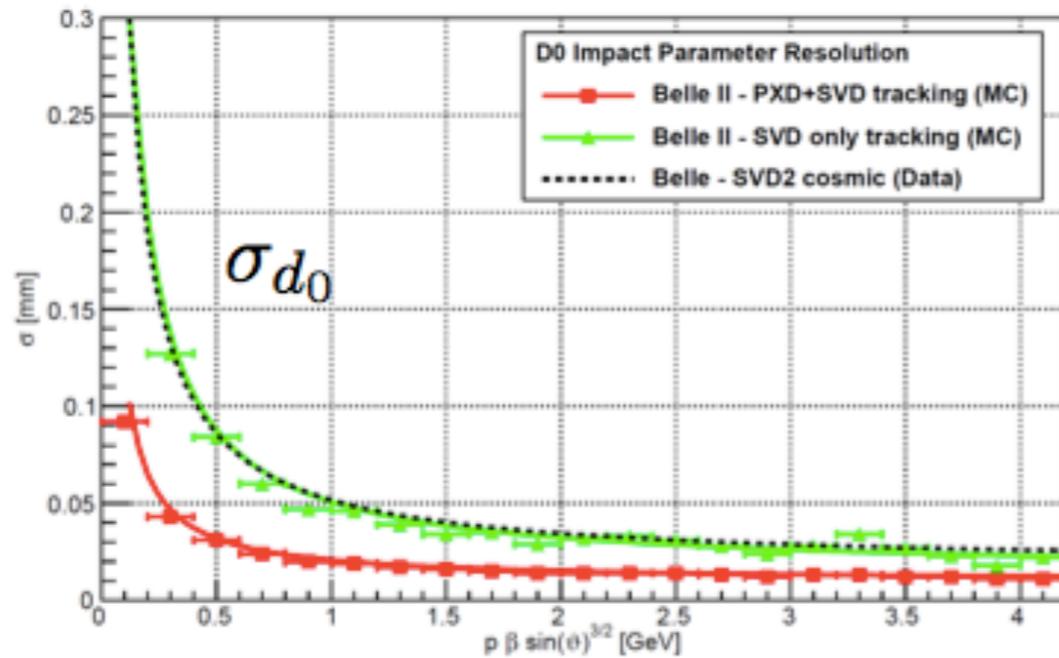
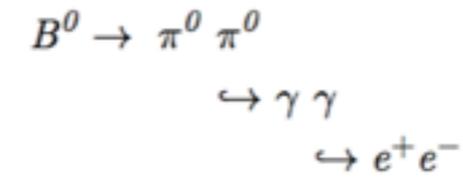
- ▶ CORE components of important experiments looking for BSM
  - ➔ **NA62**, with its GigaTracker with **micro-channel cooling** and **200ps** time resol.:  
 $K^+ \rightarrow \pi^+ \nu \bar{\nu}$  decay, SM BR:  $\sim 10^{-10}$ , 40events x 2years (2016-2018)
  - ➔  **$\mu 3e$** , featuring 2 x **0.1%  $X_0$  monolithic layers** and 1.25Gb/s links (F. Aeschenbacher):  
 $\mu^+ \rightarrow e^+ e^+ e^-$  charged-lepton flavour violation at  $10^{-16}$  (from 2019)
- ▶ and also solve puzzles from presently running experiments:
  - ➔ **Belle-II PXD**, with its two-layers of **75 $\mu$ m thick DEPFET**, to take 40xlumi of Belle to solve present anomalies in the flavour sector and look for new physics:

$$R(D^{(*)}) = \frac{\mathcal{B}(\bar{B} \rightarrow D^{(*)} \tau^- \bar{\nu}_\tau)}{\mathcal{B}(\bar{B} \rightarrow D^{(*)} \ell^- \bar{\nu}_\ell)}$$

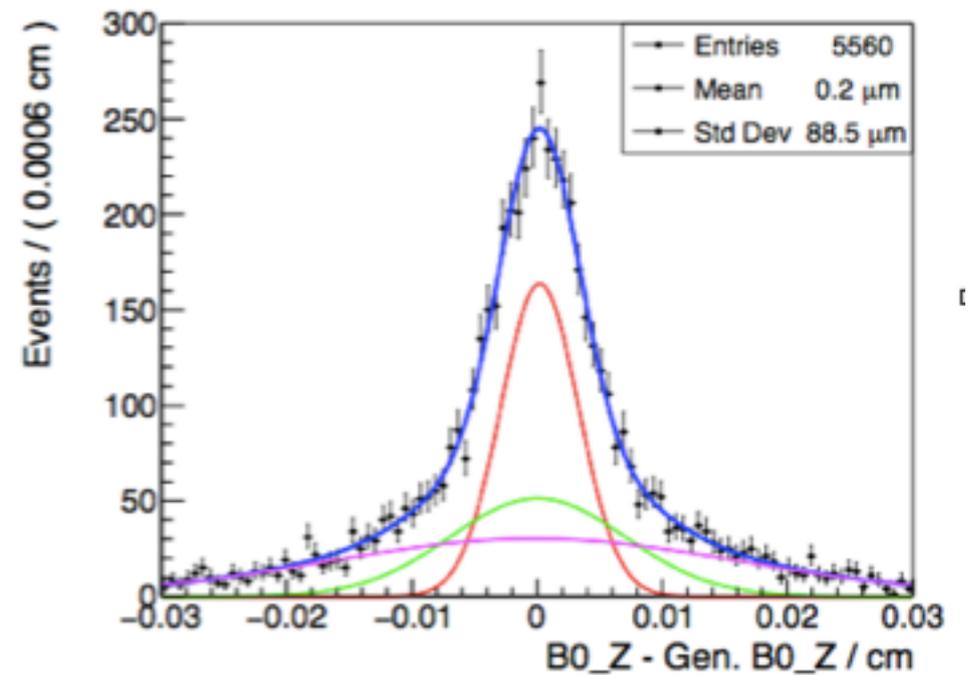
~4sigma  
discrepancy



Fernando Abudinen

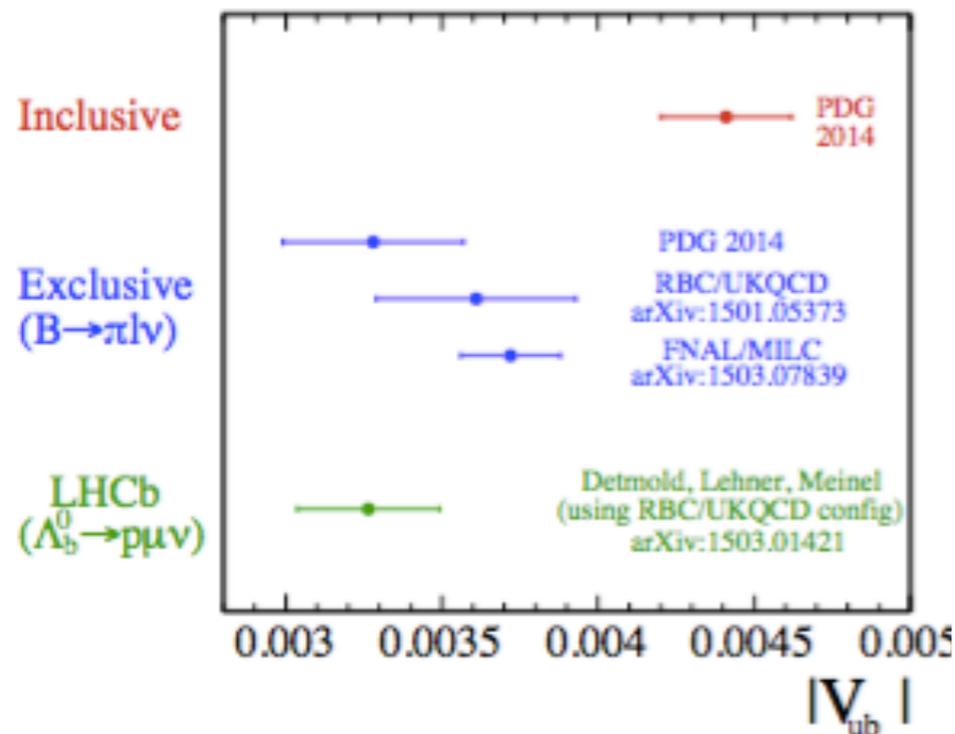
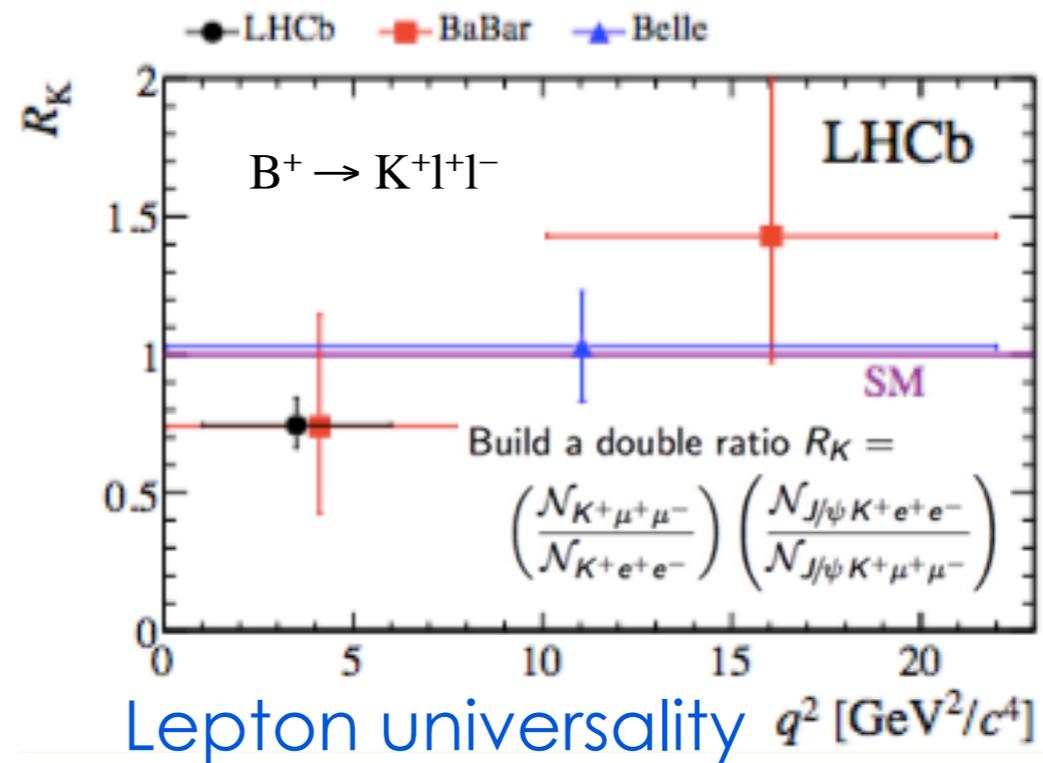
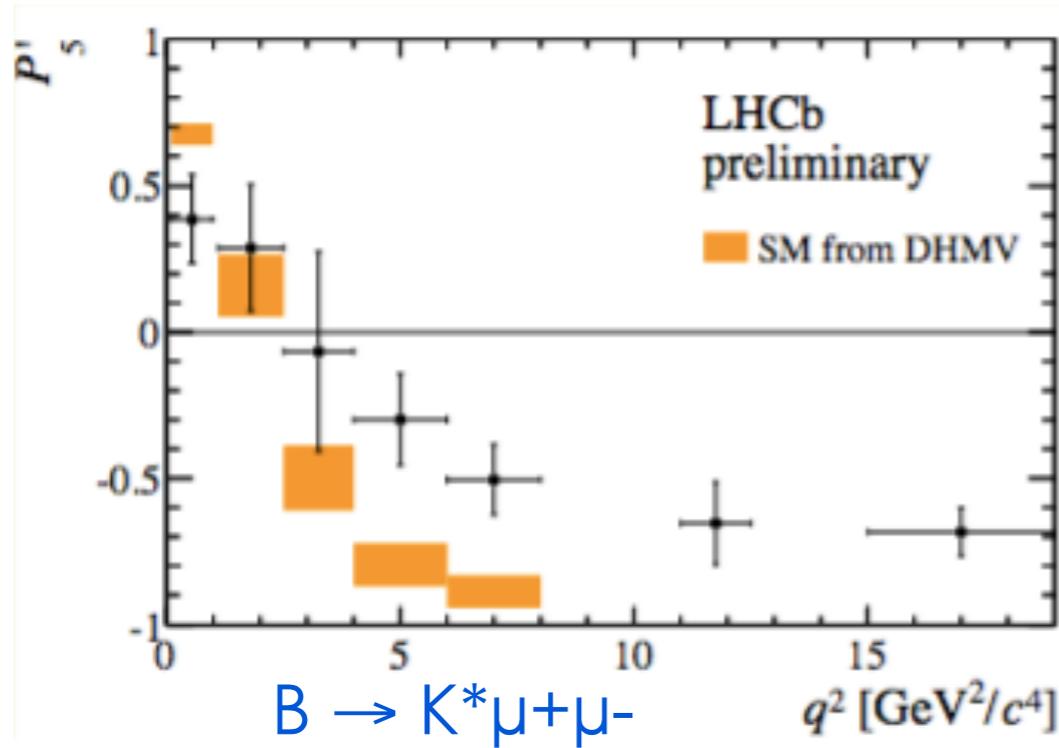


No PXD Hit required

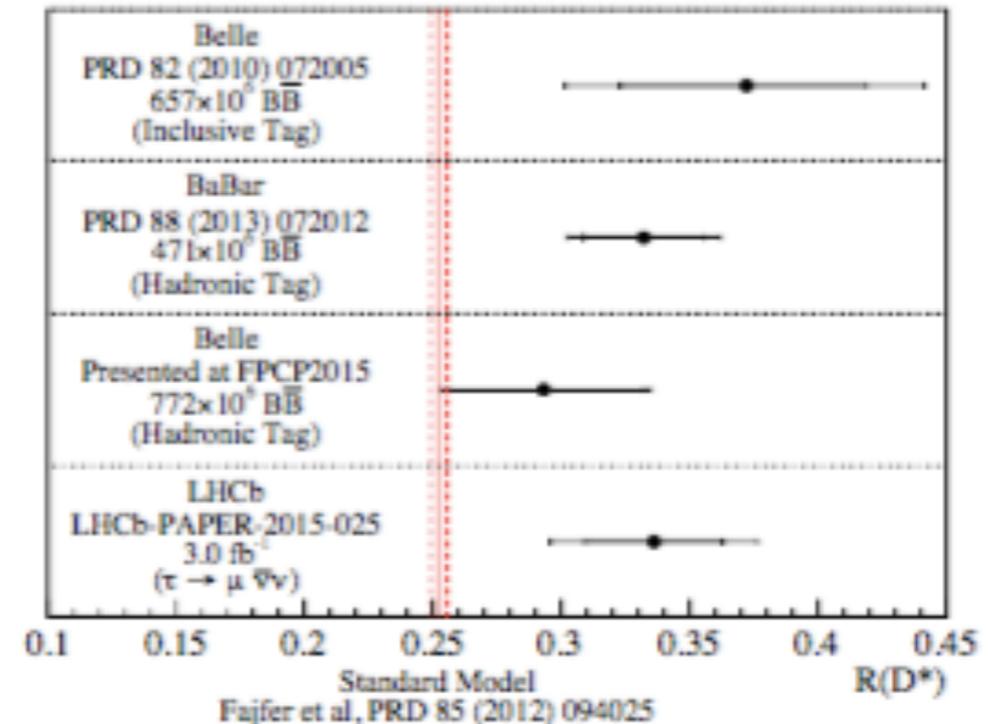


At least one track ( $e^+$  or  $e^-$ )  
has one PXD Hit

# a handful of intriguing 3-4 $\sigma$ anomalies from LHCb

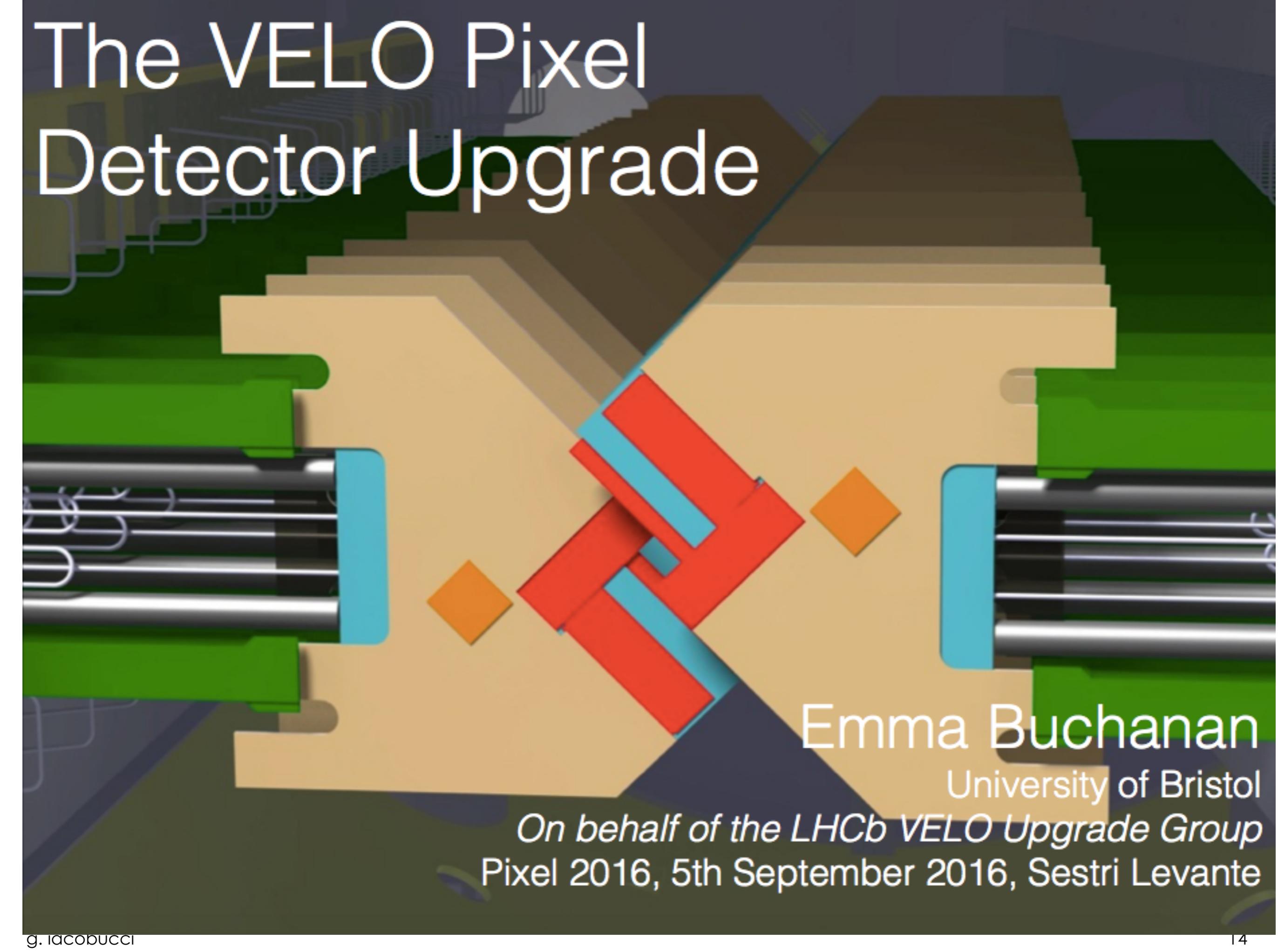


$V_{ub}$  puzzle



$B \rightarrow D^* \tau \nu$

# The VELO Pixel Detector Upgrade

A 3D schematic diagram of the VELO Pixel Detector Upgrade. The detector is shown as a central structure with a complex, multi-layered design. It features a central core of red and blue rectangular blocks, surrounded by a larger structure of tan and brown blocks. The detector is mounted on a green base, and there are several silver cylindrical components on either side, likely representing the detector's support structure or cooling system. The background is a dark blue gradient with some faint, abstract patterns.

Emma Buchanan

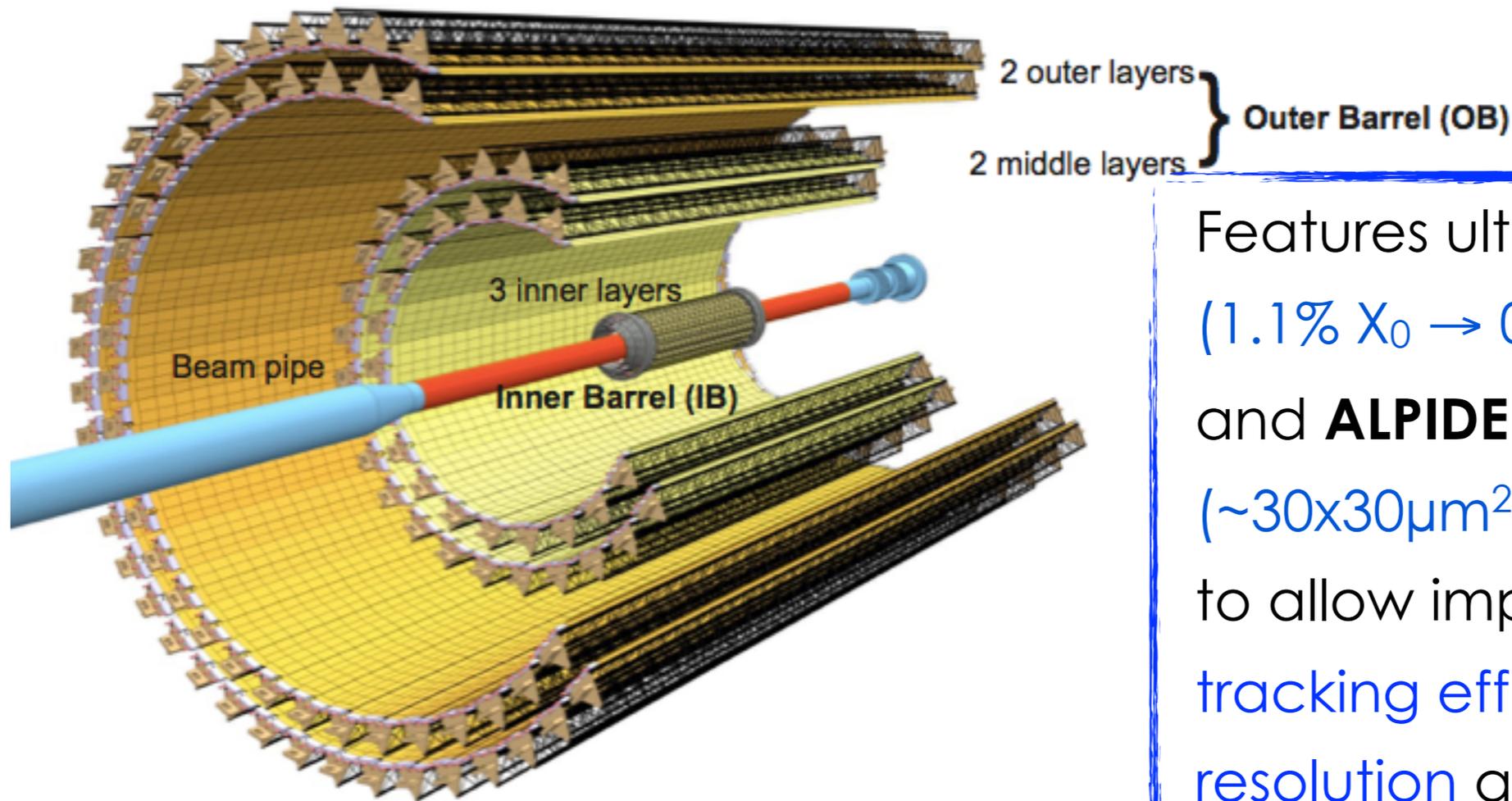
University of Bristol

*On behalf of the LHCb VELO Upgrade Group*  
Pixel 2016, 5th September 2016, Sestri Levante

- Increased statistics for improved sensitivities to very rare decays
- Limited from present 1 MHz readout  $\Rightarrow$  get rid of trigger and readout all data at 40 MHz;
  - ▶ needs upgrade of FE electronics and of tracking
  - ▶ **Pixel VERtex LOcator**: from silicon strip to hybrid pixels
    - ➔ thinner sensors (300  $\rightarrow$  200  $\mu\text{m}$ )
    - ➔ **VELOPix chip**: readout rate 40 MHz with 20Gb/s output bandwidth (130nm CMOS technology); doable since fixed-target geometry  $\Rightarrow$  material outside of acceptance volume
    - ➔ closer to the beam (8  $\rightarrow$  5.1 mm), in the secondary vacuum

Installation in 2019/2020

## The Upgraded ITS

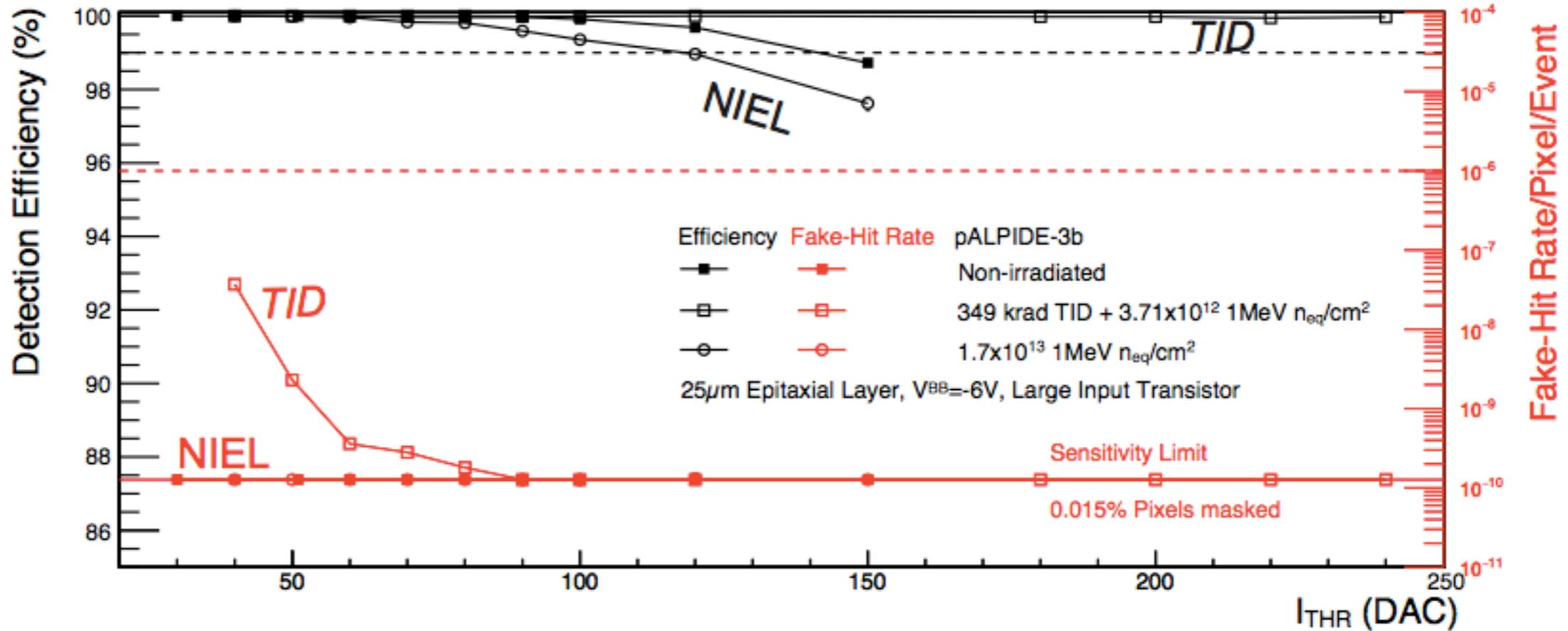


- 7 layers
- 12.5 Gigapixels
- Binary readout
- ~ 10 m<sup>2</sup> active surface

50μm thick MAPS

Features ultralight mechanics  
(1.1%  $X_0 \rightarrow 0.3\% X_0$ )  
and **ALPIDE** monolithic chip  
(~30x30μm<sup>2</sup>, 50μm thick)  
to allow improvement of  
tracking efficiency, low- $p_T$   
resolution and impact  
parameter resolution  
of a factor ~3 in  $r-\varphi$  and ~5 in  $z$   
at  $p_T=0.5\text{GeV}$ , as well as

# Test Beam Result of a Full-Scale ALPIDE Prototype



- Final pixel layout and front-end circuit selected
- Radiation effects visible
- Large operational margin maintained after NIEL and TID irradiation

Further details in **Miljenko Šuljić's talk** on Thursday

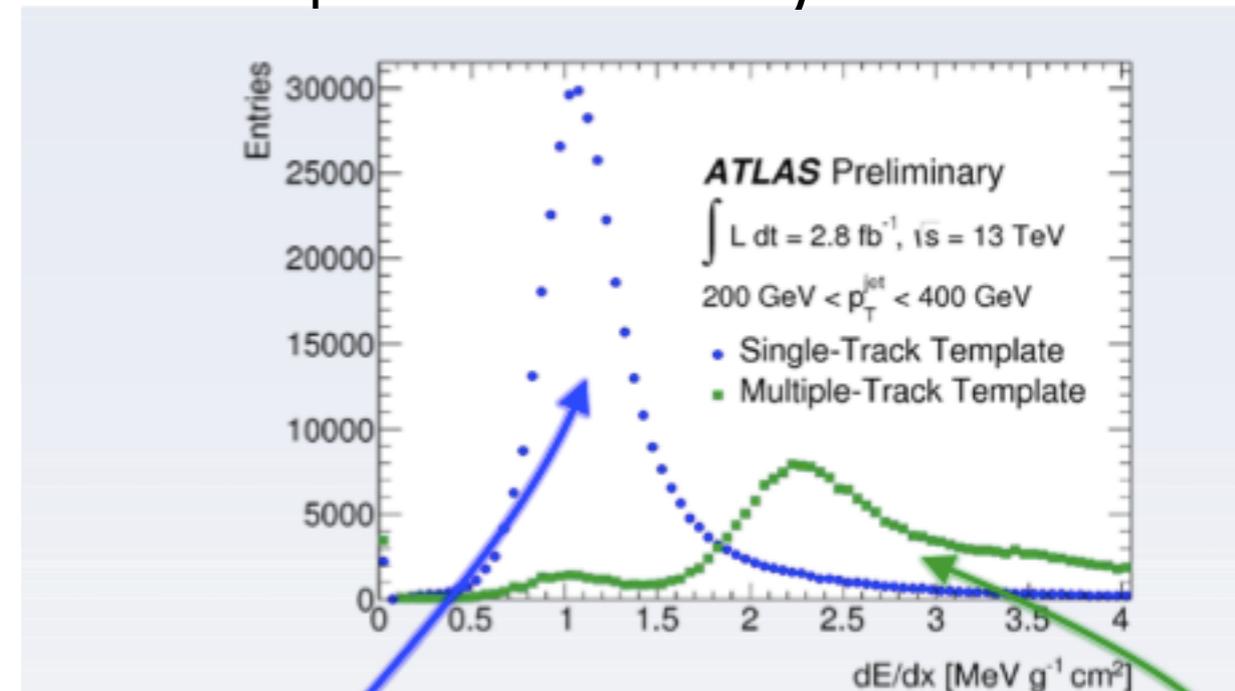
Wafers of final ALPIDE chip delivered and being tested

- In parallel to these upgrades, the experiments are seeing important steps forward in the software tools
  - ▶ for present trackers
  - ▶ and for HL-LHC trackers
  
- Pick one of the several works submitted to this workshop:

- ▶ Jason Mansur showed how T.I.D.E. for high- $p_T$  jets is important for **b-tagging** and  **$\tau$  reconstruction** as well as **boosted systems** (for which we need more and more the help of trackers)

- ➔ Artificial Neural Networks used to detect merged pixel clusters and retain tracking efficiency in jet cores.
- ➔ Data-driven method to determine fraction of lost hits in jets, that uses the pixel  $dE/dx$  measurement.
- ➔ Result: “tracking inefficiency found to be 1-3.5%, significantly improved since Run1, and in good agreement with simulation”

Again: this is one of many examples I could have taken of what can be done with present detectors by a bunch of good young scientists



- Single particle: peak at MIP energy, two particles: peak at 2x MIP energy
- Ratio of events beneath two peaks gives probability to loose track due to merging

very interesting session

09:00 - 12:35

## Pixel for x-ray science

Convener: Prof. Norbert Wermes (University of Bonn)

### 09:00 **Development of Pixel Detectors for X-ray Space Science and use in terrestrial applications** 35'

Speaker: Dr. Andrew Holland (Open University UK)

Material: [Slides](#) 

### 09:45 **JUNGFRAU: a pixel detector for Photon Science at free electron laser facilities** 12'

Speaker: Dr. Aldo Mozzanica (Paul Scherrer Institut)

Material: [Slides](#) 

### 10:00 **Low energy and high resolution performance of the MOENCH hybrid pixel detector** 12'

Speaker: Dr. Roberto Dinapoli (Paul Scherrer Institut)

### 10:15 **The EIGER detector systems** 12'

Speaker: Dr. Gemma Tinti (Paul Scherrer Institute)

### 10:30 **COFFEE BREAK** 30'

### 11:00 **Poster Session** 50'

### 11:50 **Design and Development of an Event-driven SOI Pixel Detector for X-ray Astronomy and Light Dark Matter Search** 12'

Speaker: Dr. Ayaki Takeda (Kyoto University)

Material: [Slides](#) 

### 12:05 **Evaluation of a pulse counting type SOI pixel using synchrotron radiation X-ray** 12'

Speaker: Dr. Ryo Hashimoto (High Energy Accelerator Research Organization)

Material: [Slides](#) 

### 12:20 **Development of CdTe Pixel Detectors Combined with an Aluminum Schottky Diode Sensor and Photon-Counting ASICs** 12'

Speaker: Dr. Hidenori Toyokawa (Japan Synchrotron Radiation Research Institute)

Material: [Slides](#) 

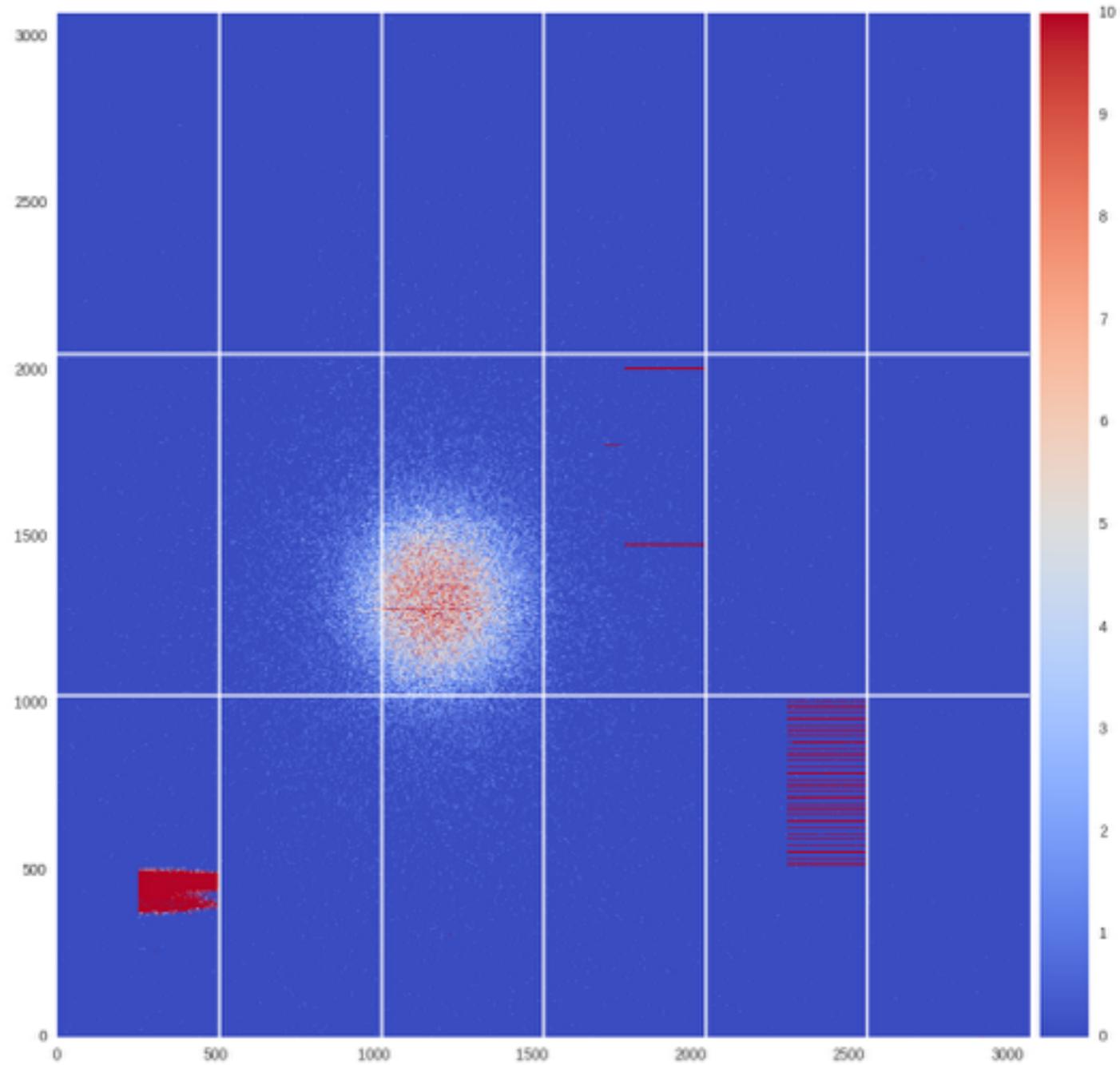
# Hybrid Detectors of the SLS Detector group



DETECTOR	Mode of operation	Pixel pitch [ $\mu\text{m}$ ]	Min. Noise [e-rms]	Maximum frame rate [kHz]	Max. Dynamic range
EIGER	SPI (Synchrotrons)	75	100	22	Up to 32 bits with summation
JUNGFRAU	CI (Synchrotrons +FELs)	75	50	2	$\sim 10^4$ 12keV photons
MOENCH	CI (Synchrotron +FELs(?))	25	35	2	$\sim 150$ 12keV photons

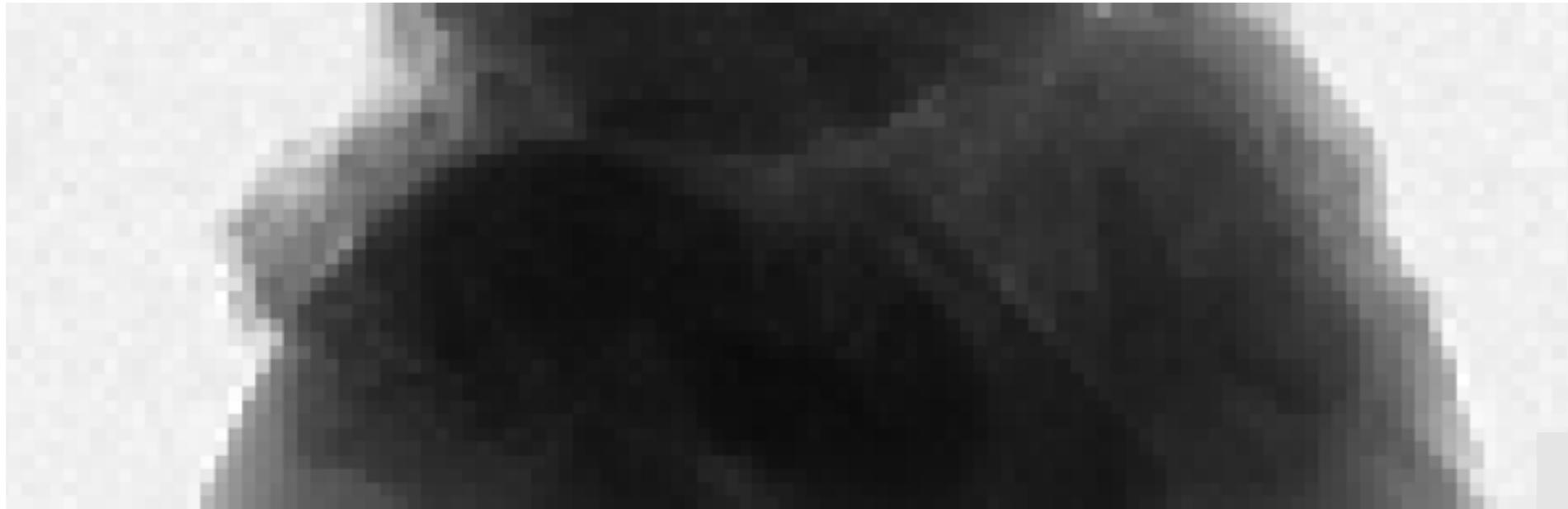
# EIGER: 9Mpixel detector (almost) ready

Sr 90 source

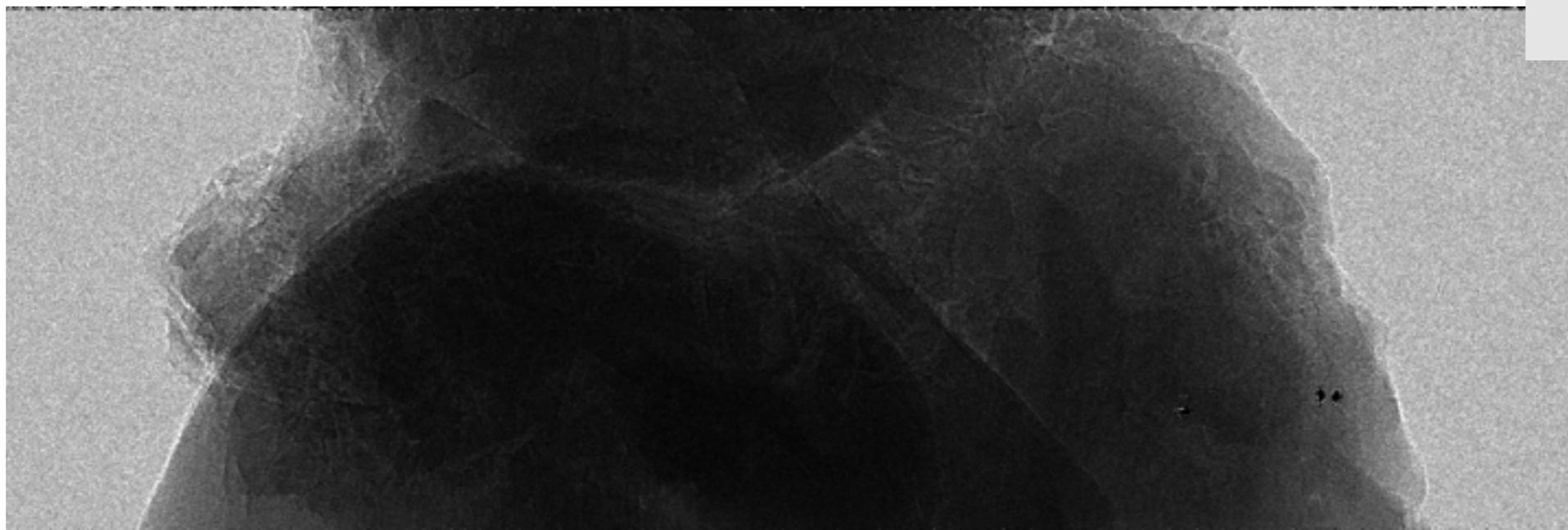


# Moench: micron resolution with interpolation

25  $\mu\text{m}$  pixels



Interpolated

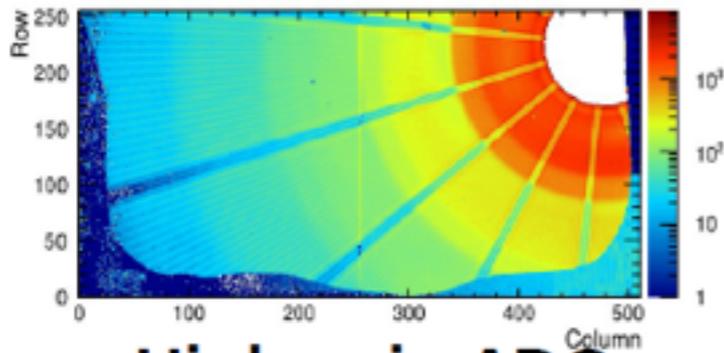
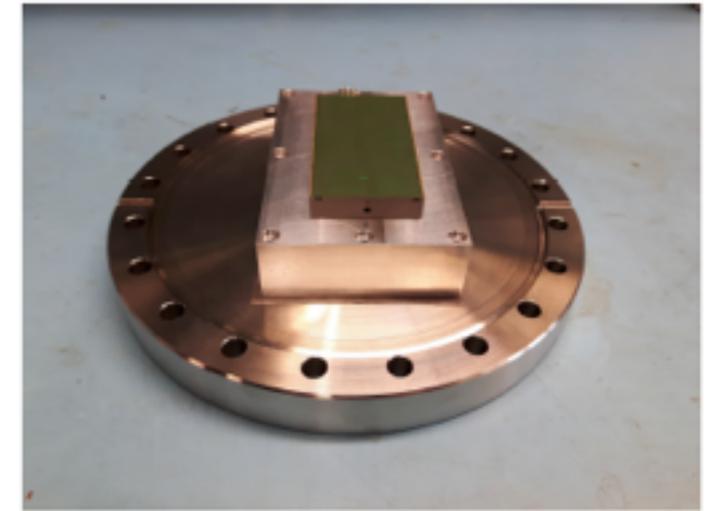


MÖNCH02  
TOMCAT 16.7 keV  
Kidney stone  
2  $\mu\text{m}$  bins

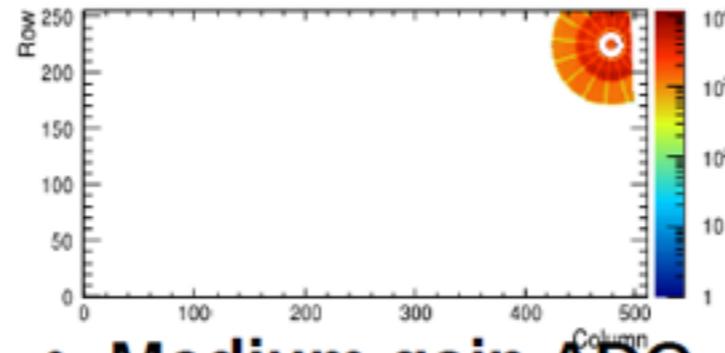
# Jungfrau: dynamic range up to $10^4$ 12keV photons

Image of Fresnel Zone Plate diffraction orders at XIL beamline, SLS:

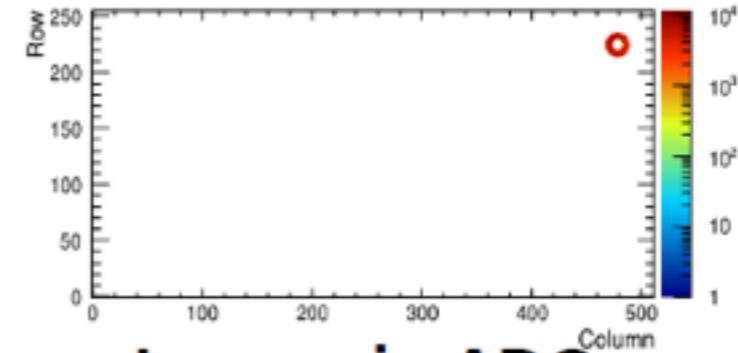
- extreme ultraviolet 92 eV photons
- vacuum  $10^{-7}$  mbar
- etched sensor (no Al), module mounted to flange



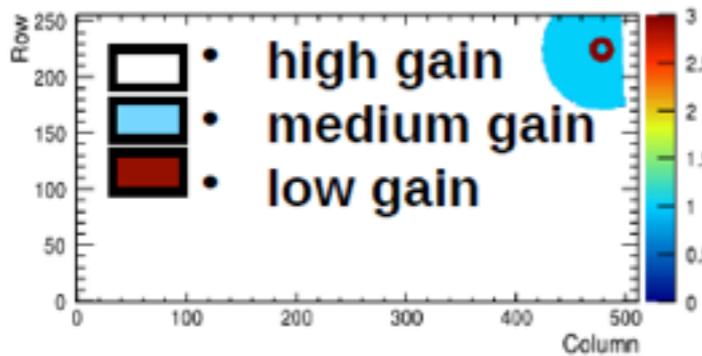
• High gain ADC



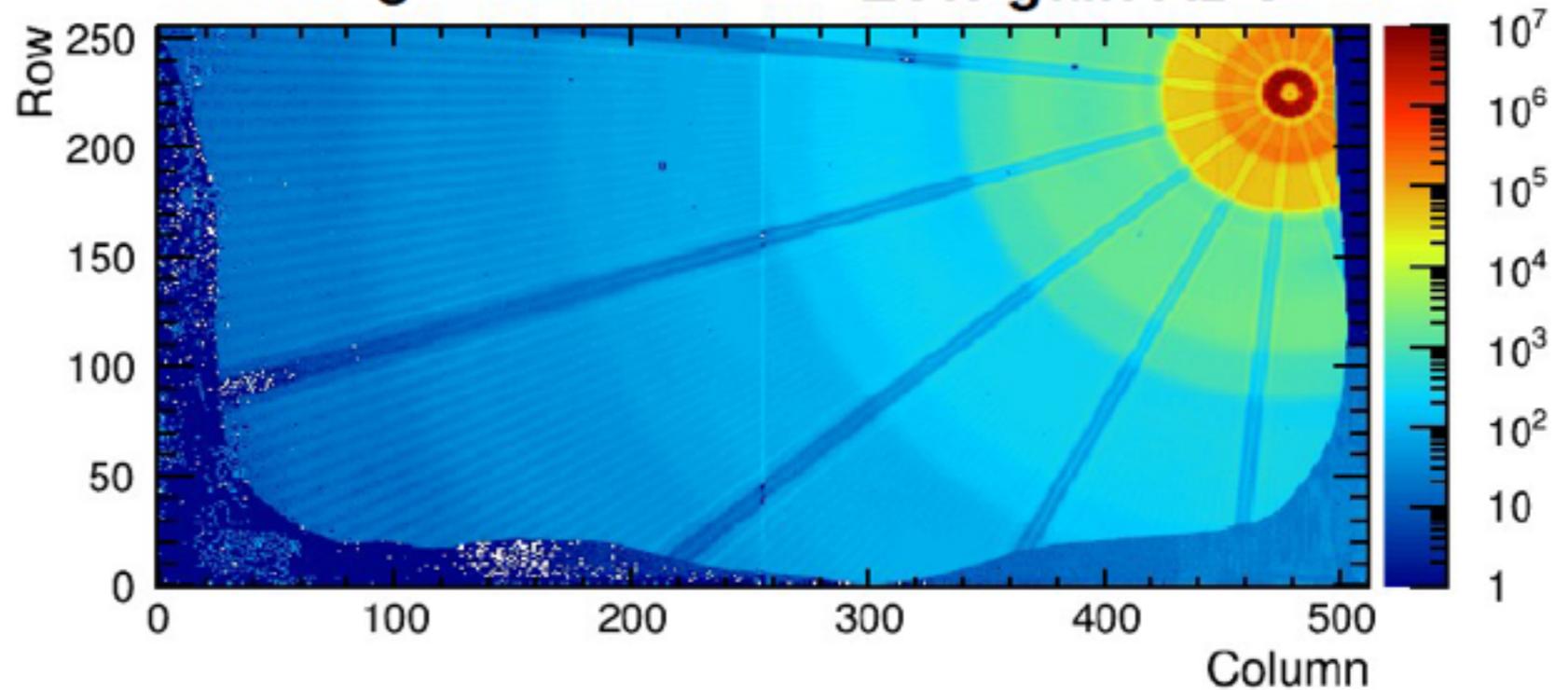
• Medium gain ADC



• Low gain ADC

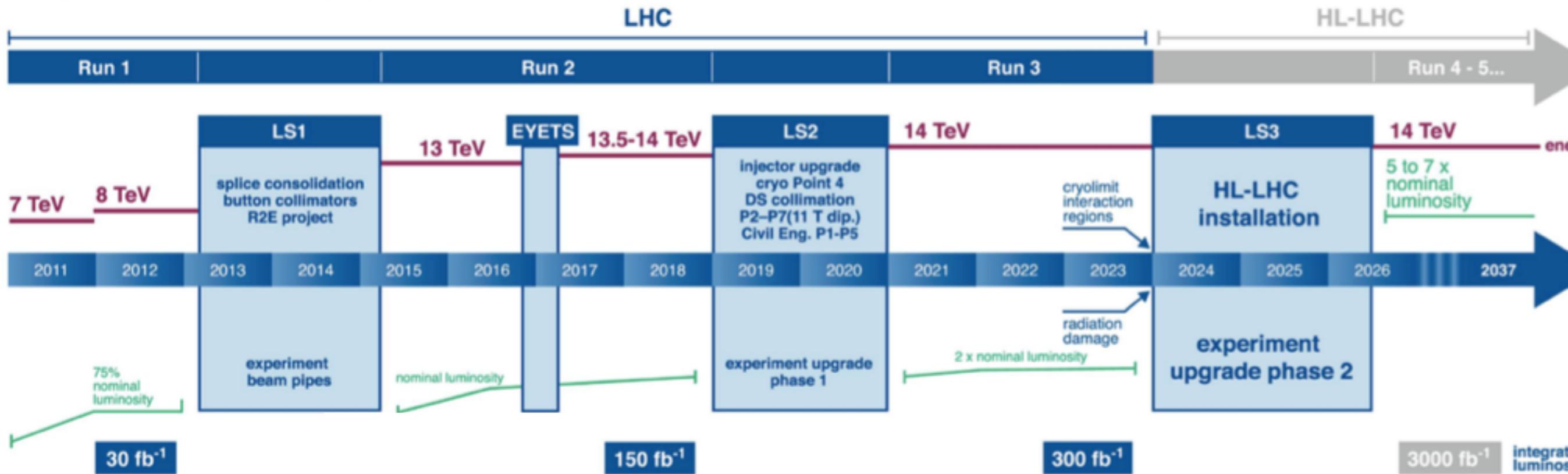


• Gain



# Do you by chance know these guys? ;)





## High-Luminosity LHC:

approved CERN project to collect 3000 fb<sup>-1</sup> (2026-2035)

- Very nice and thorough presentations on the HL-LHC conditions, challenges and progress towards the TDR's for the CMS and ATLAS pixels given by [M. Garcia-Sciveres](#) (with ref. to talks therein) and [P. Morettini](#).

## Performance



- Don't just want to do the same job with larger scale and higher intensity, want to do better!

- |  |  |
|--|--|
| • Separation of boosted objects                                      | → Higher granularity yes, but can go further using clusters (Mansour, 9:15)                          |
| • Suppression of pileup activity                                     | → Z-vertex separation (Smart, Migliore), timing (Seiden, Cartiglia; Mon., Neri, 12:10, Mulargua [P]) |
| • Higher rapidity coverage   | → Innovative layouts (Smart, Migliore)<br>Which need lighter services!                               |
| • Much higher trigger rate<br>(all events look the same at high p/u) | → Readout, track triggers<br>Morettini, Kornmayer, Neri, 11:05)                                      |
| • Lower mass (also services)   | → Better cooling, new materials<br>(Anderssen, Verlaat, Fri. 9, 10)                                  |
| • Faster pattern recognition   | → Dedicated hardware, Use more information<br>(clusters shapes, timing)                              |

## Enormous challenges. Not exhaustive list of challenges:

- ▶ **Data extraction:** 40MHz readout (like Cal and Muon) impossible for innermost pixel layers since at  $R=39\text{mm}$   $\sim 1\text{Gb/s}$  per  $\text{cm}^2$  and per triggered MHz
  - ➔ at 40 MHz, would need to transfer  $\sim 160\text{Gb/s}$  per chip !
  - ➔ Since optical conversion stages not radhard enough we should fill the detectors with cables ! That we certainly do not want to do.
  - ➔ put optical links outside detector volume
  - ➔ use flex, twisted-pairs or micro-coaxial cables
  - ➔  **$\sim 5\text{Gb/s/chip}$  possible** over a length of  $\sim 5\text{m}$   $\Rightarrow$  trigger rate of  $\sim 1\text{MHz}$
  - ➔ readout chip: need small feature (65nm) technology
- ▶ **Trigger:** two approaches
  - ➔ self seeded tracklets (CMS) ( $\rightarrow$  E. Migliore)
  - ➔ two-stage (L0/L1) trigger (CAL+MUON at 40MHz, tracker at  $\sim 1\text{MHz}$ , ATLAS) ( $\rightarrow$  P. Morettini)

**Enormous challenges.** Not exhaustive list of challenges:

▶ **Mechanics, cooling:**

Two main enabling technologies for HL-LHC:

- CO<sub>2</sub> Evaporative Cooling → B. Verlaet
- High thermal conductivity materials and adhesives  
→ E. Anderssen

▶ **Powering:** serial power distribution (under development) seems the only possible solution

▶ **Radiation doses:** **1 Grad** and  **$1.4 \times 10^{16} n_{eq} \text{ cm}^{-2}$**  in innermost layer (R=39mm)

➔ **3D sensors:** 97.8% efficient and 15mW/cm<sup>2</sup> at  $10^{16} n_{eq} \text{ cm}^{-2}$  for IBL/AFP sensors; HL-LHC (50x50μm<sup>2</sup>) submitted (→ J. Lange). Question on production capability ??

➔ **planar:** 100μm thin n-in-p ~97% and 25mW/cm<sup>2</sup> at  $10^{16} n_{eq} \text{ cm}^{-2}$  (→ A. Macchiolo). See very interesting talks by Nobu, Andrea and Richard on their recent work.

➔ **CMOS:** very active community, many solutions being studied. I'll comment later.

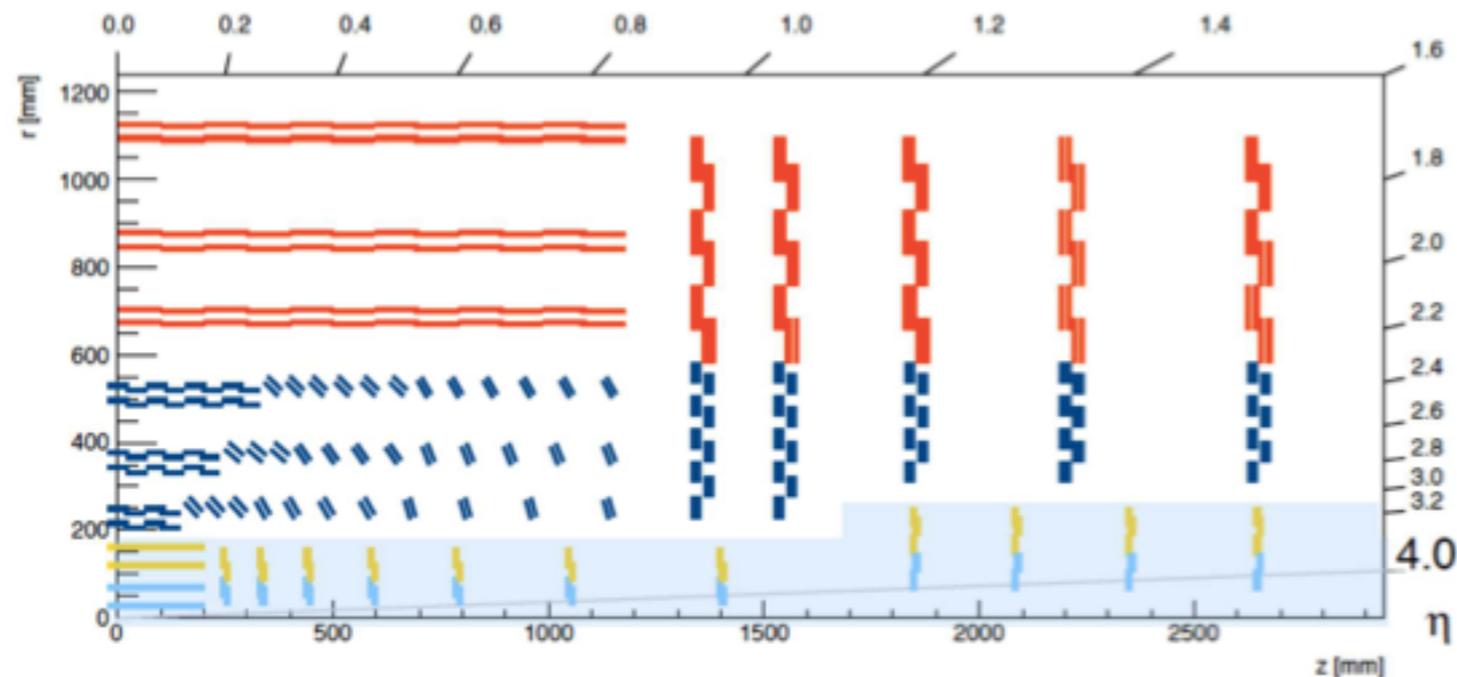
# CMS Pixel Detector design for HL-LHC

E.Migliore  
Università di Torino/INFN

on behalf of the CMS Collaboration



# The CMS Tracker in the HL-LHC scenario

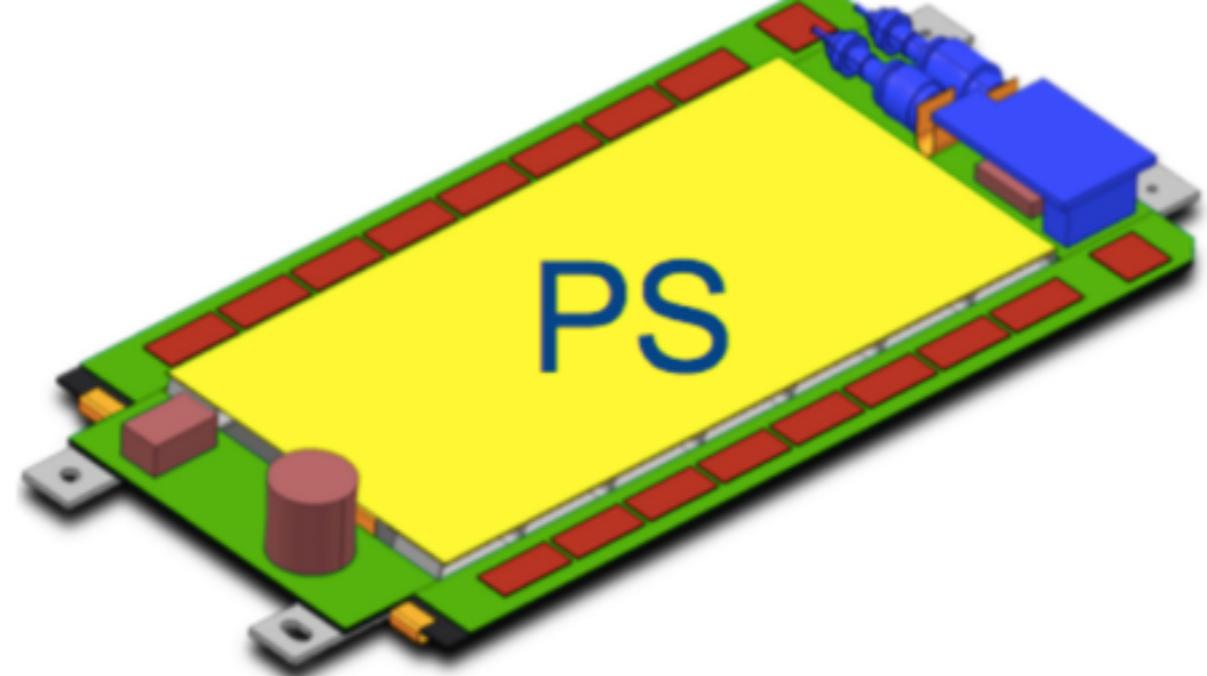


- Additional functional requirements for the overall Tracker:

REQUIREMENT	MOTIVATION
extended coverage	contribute to pileup mitigation (PF) up to $ \eta  \sim 4$
high granularity	robust two track separation in high energy jet
low material budget	improve tracking performance/momentum resolution measurement
measure $p_T > 2$ GeV tracks at 40 MHz	contribute to L1 trigger
deep front end buffers and higher readout bandwidth	compatible with $12.5 \mu\text{s}$ L1A latency and 750 kHz L1A trigger rate

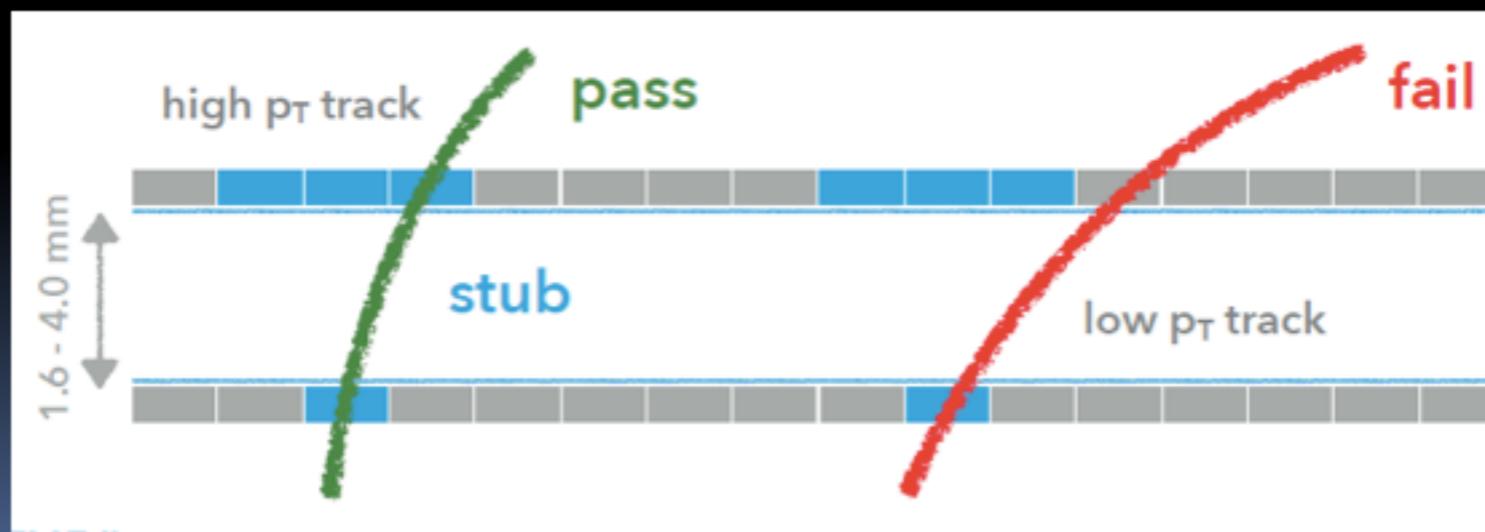
They all have implications on the design of the Inner Pixel!

## CMS track trigger Pixel-Strip module



### Self-seeded detectors

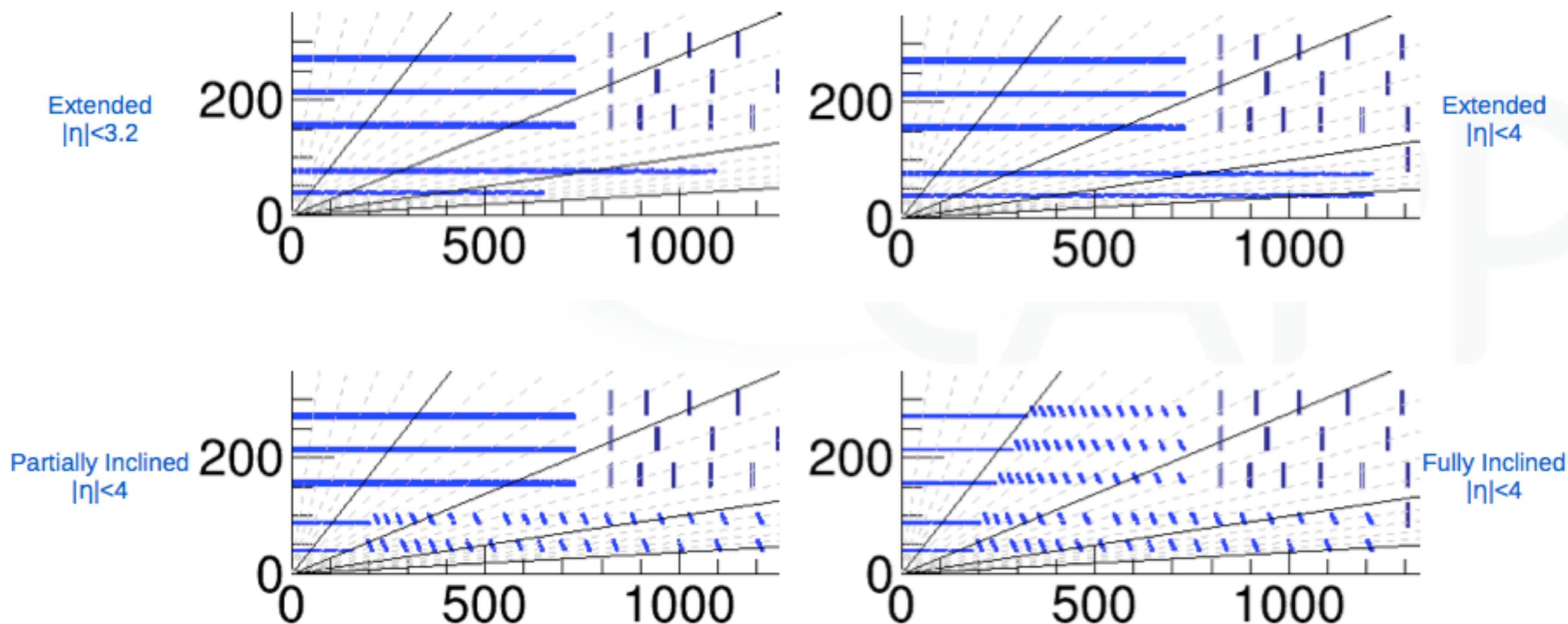
- The approach used in the CMS Pixel-Strip and Strip-Strip **doublets**, in the outer tracker. Here **macro-pixels** ( $100\ \mu\text{m} \times 1.5\ \text{mm}$ ) are used to get precise  $z$  measurement.
- The **correlation between two layers** can identify high momentum tracks and send them to the trigger processor.
- This approach benefits from **the intense CMS magnetic field**.



# Collection of arguments from E. Migliore talk

- Current baseline: planar sensors
  - n-on-p substrate current detector n-on-n
  - thin sensors ( $100 \mu\text{m} \leq d \leq 200 \mu\text{m}$ ) current detector  $285 \mu\text{m}$
  - small pitch pixel cell ( $2500 \mu\text{m}^2$  area) current detector  $15000 \mu\text{m}^2$  area
- Usage of 3D sensors is an option for the layers more exposed to radiation damage.  
Sensors with small pitch 3D pixels available (from CNM and FBK).  
Currently processed for bump-bonding of the readout chip.
- Preliminary indications from full-simulation studies on the aspect ratio:  
in BPIX better performance of **rectangular** pixels compared to **square** pixels:
- Last year has seen a focused but considerable effort to converge toward a realistic design of the CMS Inner Pixel for the TDR.
- Key points which will be clarified by R&D activities in the next months:
  - performance of small pitch pixels before/after irradiation
  - performance of 65 nm ROC
  - performance of serial powering

- Four layouts are under consideration for the ITk pixel barrel:  
Two 'extended' layouts (sensors parallel or perpendicular to beam line).  
Two 'inclined' layouts (with sensors also angled towards the beam-spot).



- All layouts consist of five pixel barrel layers.

and now the holy grail:

NEW  
SENSOR  
TECHNOLOGIES

# Everybody is discussing:

CMOS

CMOS

CMOS

CMOS

CMOS

CMOS

CMOS

CMOS

CMOS

- How can ATLAS & CMS take advantage of CMOS sensors ?
  - ➔ passive CMOS sensors bonded to readout chip → production in ~weeks
  - ➔ CCPD: smart CMOS sensor glued to readout chip → very high yield
  - ➔ fully monolithic: already a reality in HEP with STAR, mu3e, ALICE → take advantage of RD53
  - pixel encoding possible
- Several (maybe too many ??) designs and foundries
  - ▶ “all of them will work”; testbeam measurements of few mm<sup>2</sup> hv-cmos chips shows: **99.7% effic. at 10<sup>15</sup> neq/cm<sup>2</sup>** with good timing;  
Recent ATLAS 2x2cm<sup>2</sup> submissions (CCPD & MAPS) to AMS and LFoundry
  - ▶ Showstoppers ? Can't see for the moment. Still lot of work to do to qualify but large margin to fit all HL-LHC requirements.  
Maybe more collaborative effort needed to qualify them in time (~2018)?

Great contribution from the **CLIC** community, although different requirements (→ see talk of Andreas Nürnberg)

# Everybody is discussing:

Timing

Timing

Timing

Timing

Timing

Timing

Timing

Timing

Timing

# The 4D pixel challenge

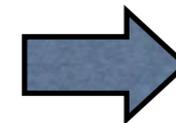
Is it possible to build a tracker with concurrent excellent time and position resolution?



Can we provide from the same detector and readout chain:

**Timing resolution ~ 10 ps**  
**Space resolution ~ 10's of  $\mu\text{m}$**

Tracking in 4 Dimensions

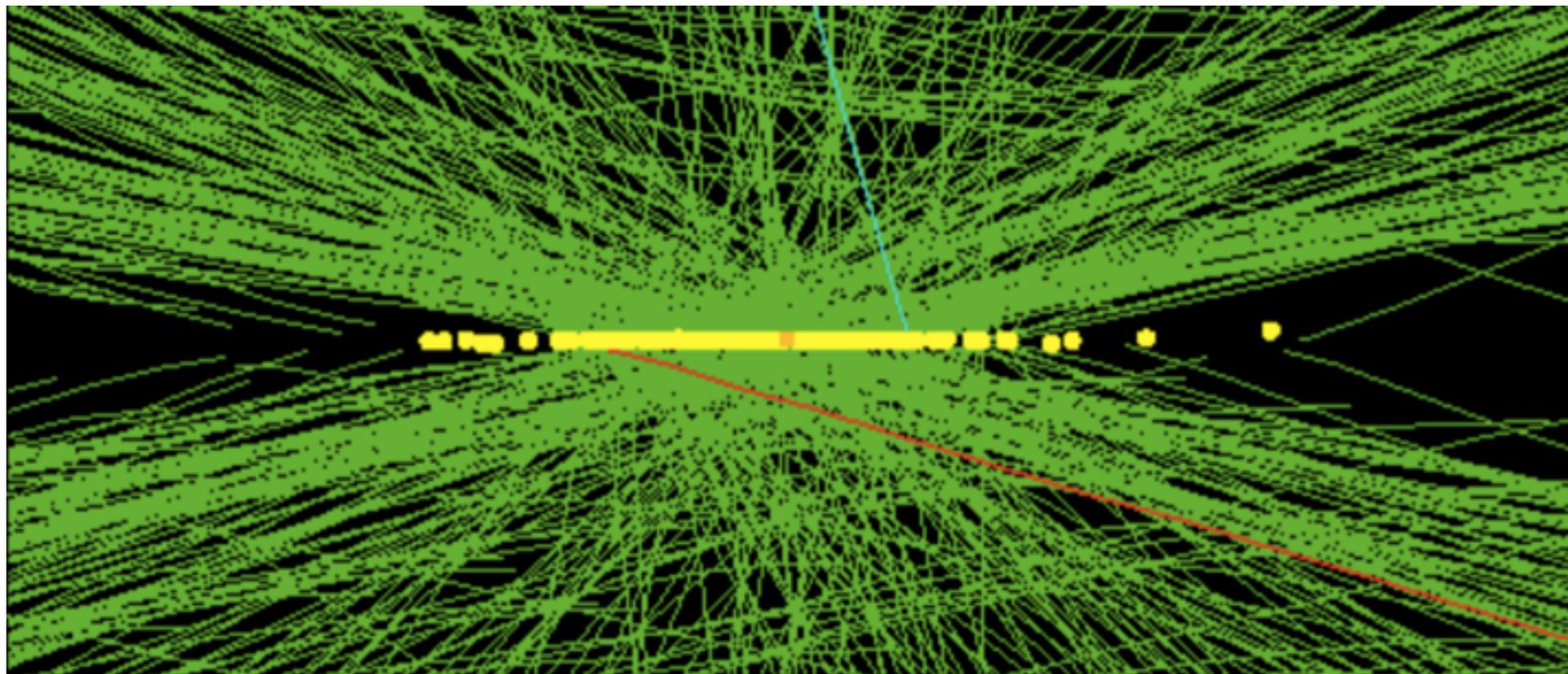


Is it important for the HL-LHC ??

At the HL-LHC

with 200 events pileup:

- **Time RMS between vertexes: 153 ps**
- **Average distance between two vertexes: 500 um**
- **Fraction of overlapping vertexes: 10-20%**
  - Of those events, a large fraction will have significant degradation of the quality of reconstruction



- ▶ fast and accurate pattern recognition
- ▶ pileup mitigation, by association of tracks to the hard vertex
  - ➔ need excellent  $Z_0$  impact parameter resolution
  - ➔ but only  $\sim 10$ ps timing can resolve events overlapping in  $Z$

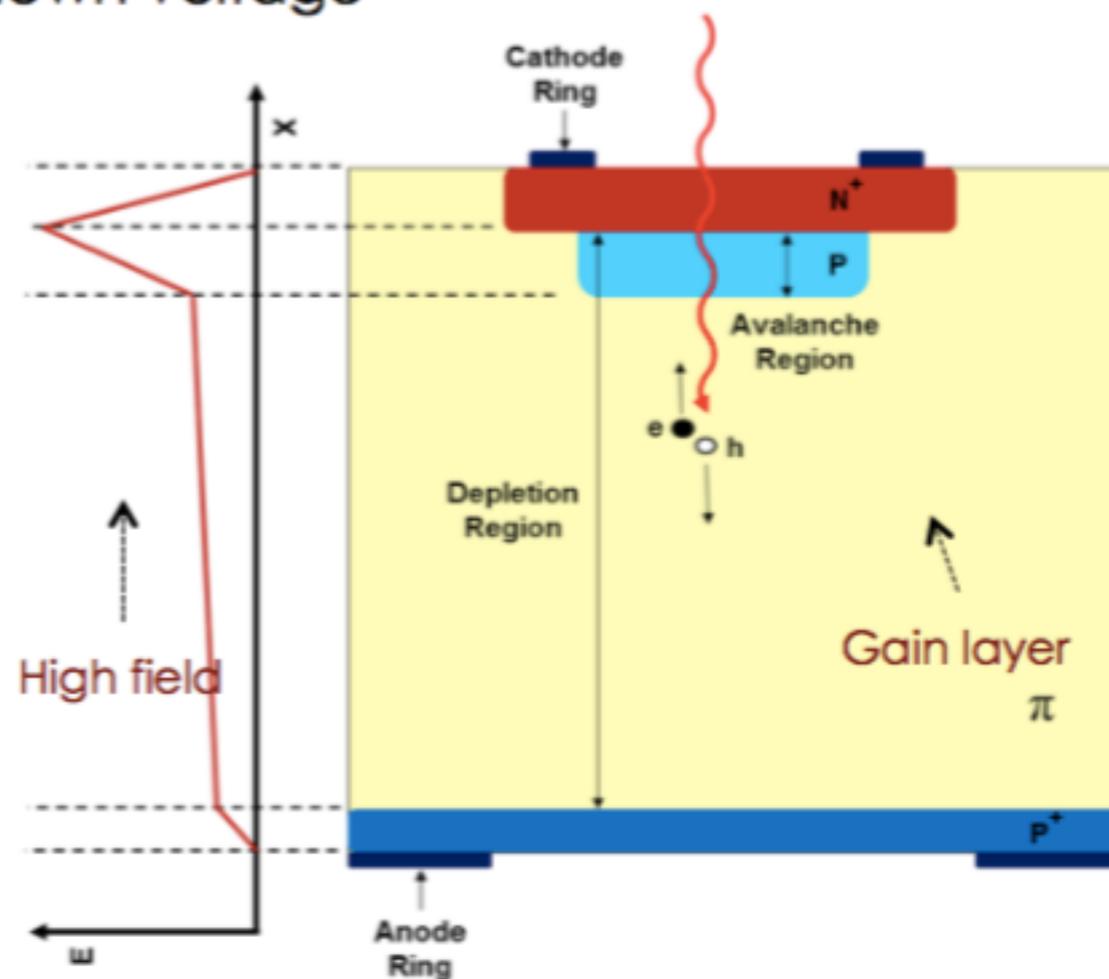
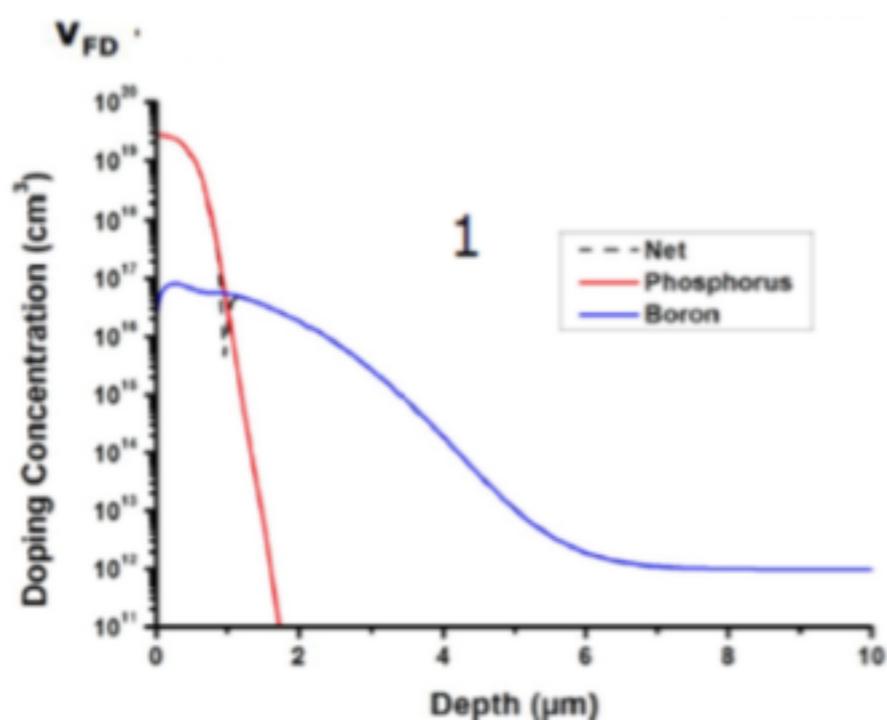
# Low Gain Avalanche Detectors (LGADs)

The LGAD sensors, as proposed and manufactured by CNM

(National Center for Micro-electronics, Barcelona):

**High field obtained by adding an extra doping layer**

$E \sim 300$  kV/cm, closed to breakdown voltage



Adding a highly doped, thin layer of of **p-implant** near the p-n junction creates a high electric field that accelerates the electrons enough to start multiplication. Same principle of APD, but with much lower gain.

# Ultra Fast Silicon Detectors

**UFSD are LGAD detectors optimized to achieve the best possible time resolution**

## **Specifically:**

1. Thin to maximize the slew rate ( $dV/dt$ )
2. Parallel plate – like geometries (pixels..) for most uniform weighting field
3. High electric field to maximize the drift velocity
4. Highest possible resistivity to have uniform E field
5. Small size to keep the capacitance low
6. Small volumes to keep the leakage current low (shot noise)

# Sensors: FBK & CNM

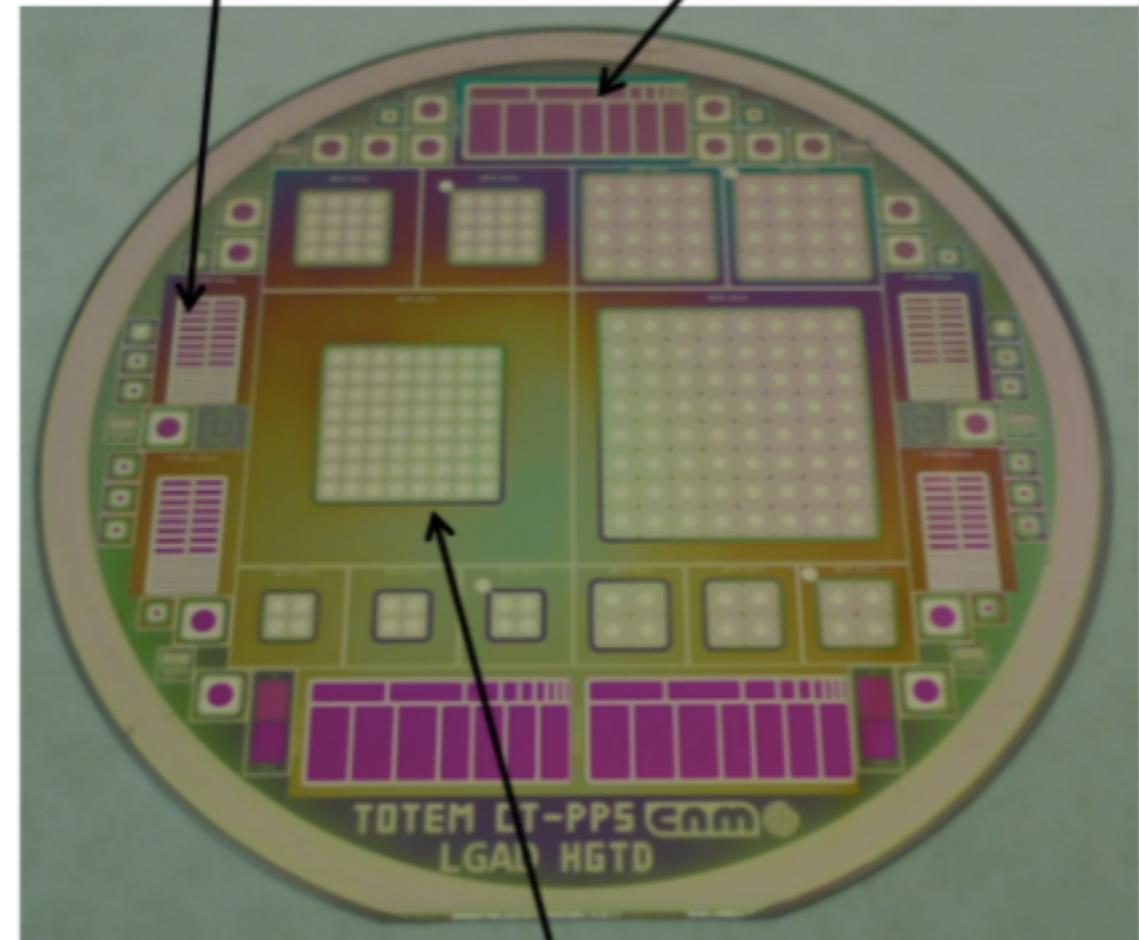
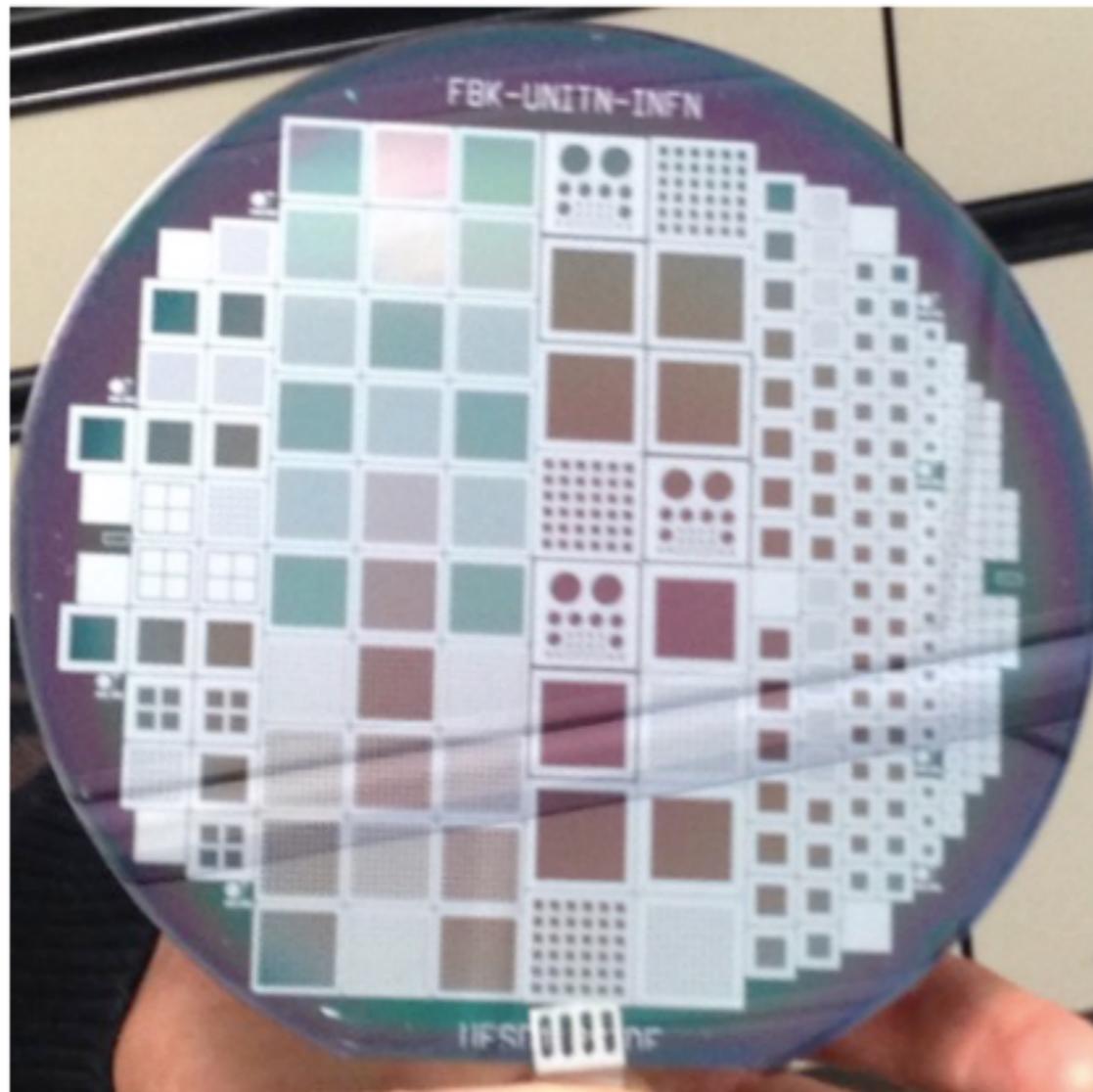
FBK 300-micron production  
Very successful, good gain and overall behavior

➔ We have now a second producer

CNM 75-micron  
CNM 50-micron production

x4 CT-PPS

x3 TOTEM



ATLAS High Granularity Timing Det.

N. Cartiglia, INFN, Torino - 4D pixel - Sestri 2016

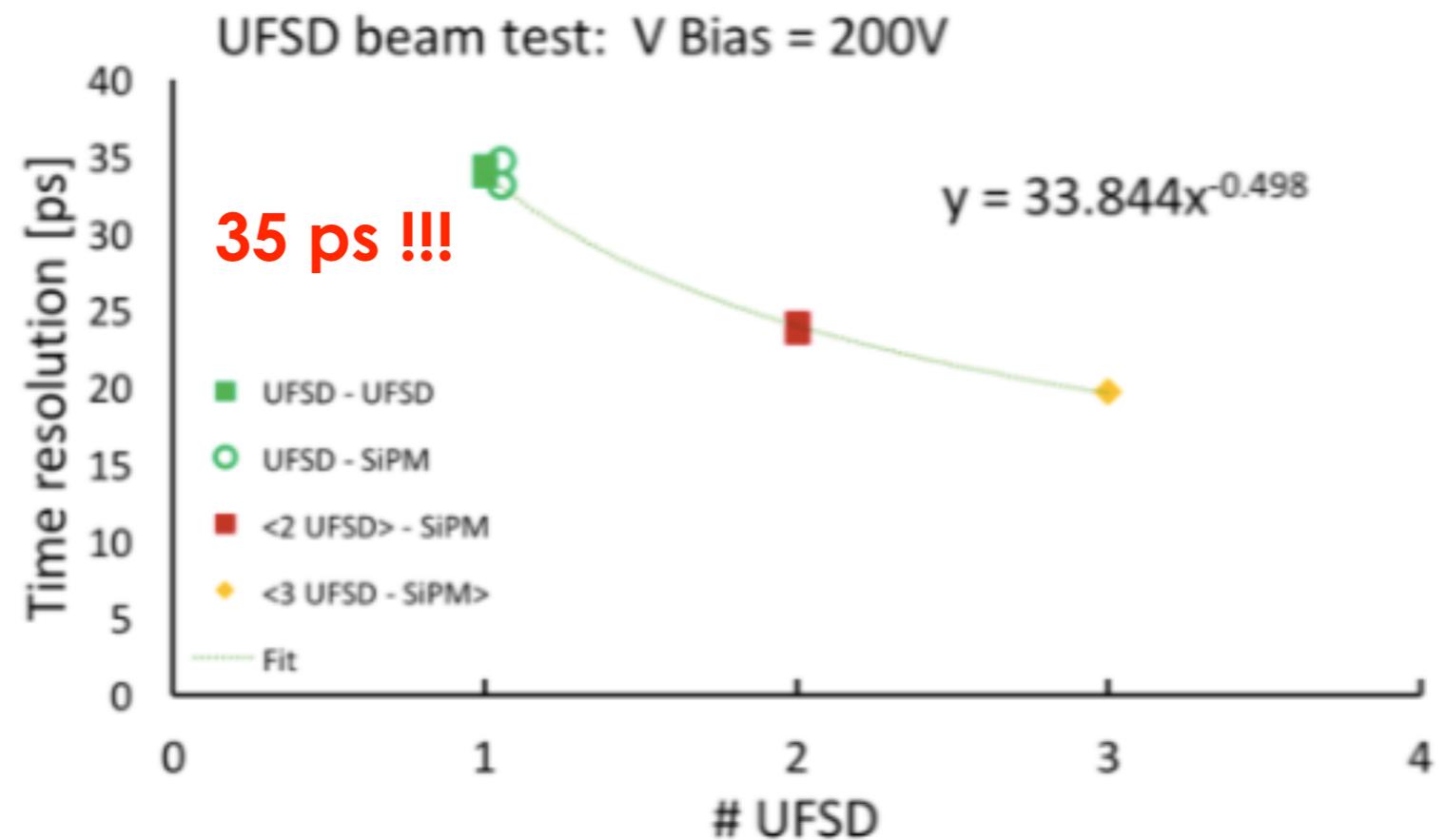
# 2016 CERN testbeam of

CNM-UFSD 1.2 x 1.2 mm<sup>2</sup>, 50μm thick (C = 3pF, Gain = 15)

Time resolution as difference w.r.t. very accurate (~15ps) SiPM

## Multiple UFSD tracking system

Timing Resolution [ps]		
Vbias [V]	200V	240V
N=1 :	34.6	25.6
N=2 :	23.9	18.0
N=3 :	19.7	14.8



Submitted to NIMA

<http://arxiv.org/abs/1608.08681v1>

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Next steps:

- Radiation hard studies
- Electronics for larger sensors (20-30 pF)

- Pixel detectors became more and more important for present and future experiments
  - ▶ large variety, following the physics requirements
  - ▶ software progress
  - ▶ hardware (mechanics/sensor/readout/services) progress
- The prohibitive HL-LHC requirements is a challenge also for the good-old hybrid pixels
- CMOS and  $\sim 10$ ps tim resolution are the new eldorado
  - ▶ Hard to say if we will manage to benefit from these new technologies at the HL-LHC